

# EVAFLEX® 5-VS

オートロック、高温対応(105°C)、高速伝送対応、水平嵌合、0.5 mmピッチ、シールドFFC/FPCコネクタ

## Product Specifications:

Board Pitch (mm)	0.5	
Wiping Length (mm)	1.1	
Size (mm)	Height	1.90 +/- 0.10
	Width	Formula: 6.25 + (0.5*?p)
	Depth	4.95 +/- 0.20
Pin counts	Range	10 - 50
	Available	10, 15, 20, 24, 30, 40, 50

## Applicable FPC/FFC:

FPC/FFC Type	Shielded FFC, Non-shielded FFC/FPC
FPC/FFC Contact Point	Top
FPC/FFC Thickness (mm)	0.33 +/- 0.03

## Applicable Standards (Reference Only):

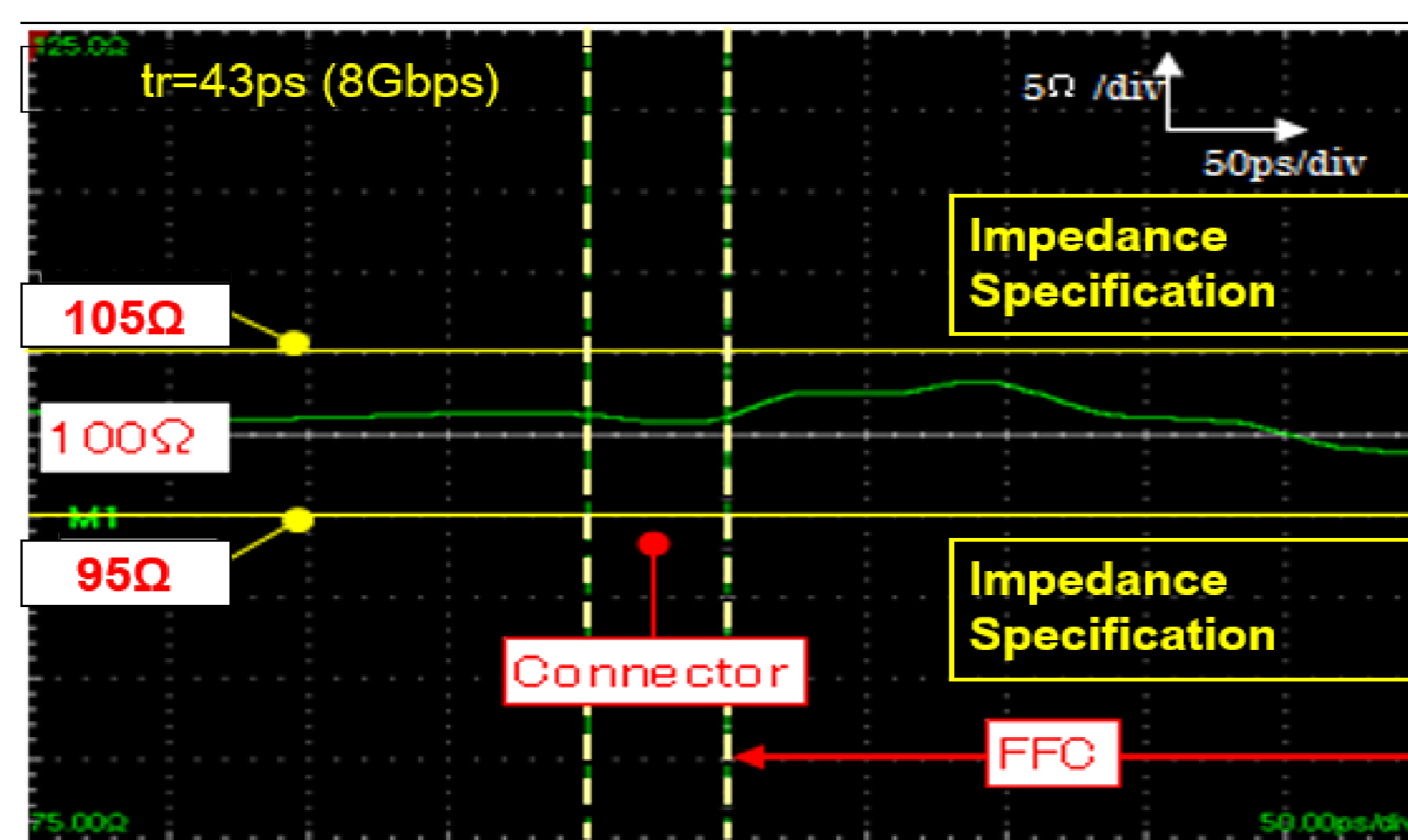
USB 3.1 Gen 1 (5 Gbps) eDP HBR 3 (8.1 Gbps) eDP HBR 2 (5.4 Gbps) eDP (2.7 Gbps) HDMI 2.0 (6 Gbps) V-By-One HS 1.4 (4 Gbps) MiPi standards  
USCAR II Vibration & Shock V1

\*記載のない極数の対応状況についてはお問い合わせください。



## ▶ 8+ Gbpsの高速信号をサポート

立上り時間(tr) vs インピーダンス特性



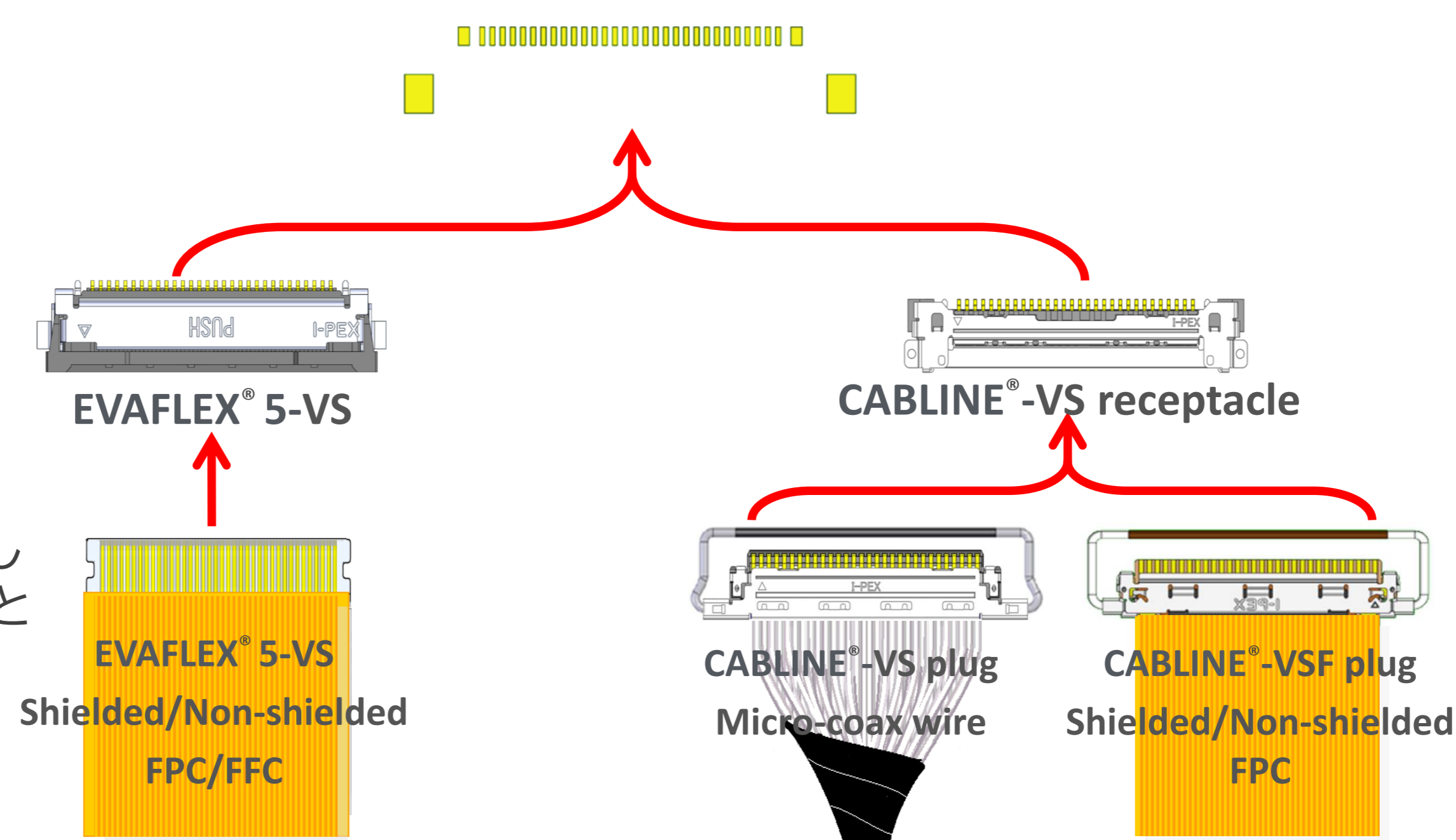
試験条件:

ダブルサイドシールドFFC  
100 ohmマッチング

PCI Express® 3.0 (8 Gbps)

## ▶ CABLINE®-VS (VESA規格の標準コネクタ)とフットプリント共通化

EVAFLEX® 5-VSは、VESA規格のCABLINE®-VSレセプタクルを使用して同じPCBレイアウトに取り付けることができます



## ▶ 拡張性の高いEVAFLEX®シリーズでオートロックを始め様々なオプションに対応

高速伝送 & EMIシールド対応: EVAFLEX® 5-HD

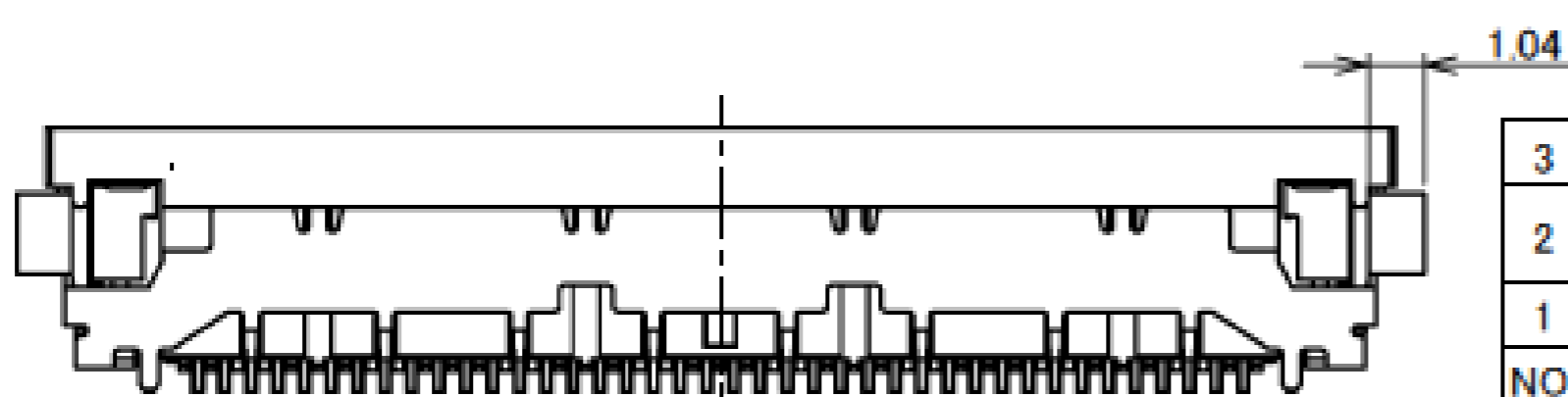
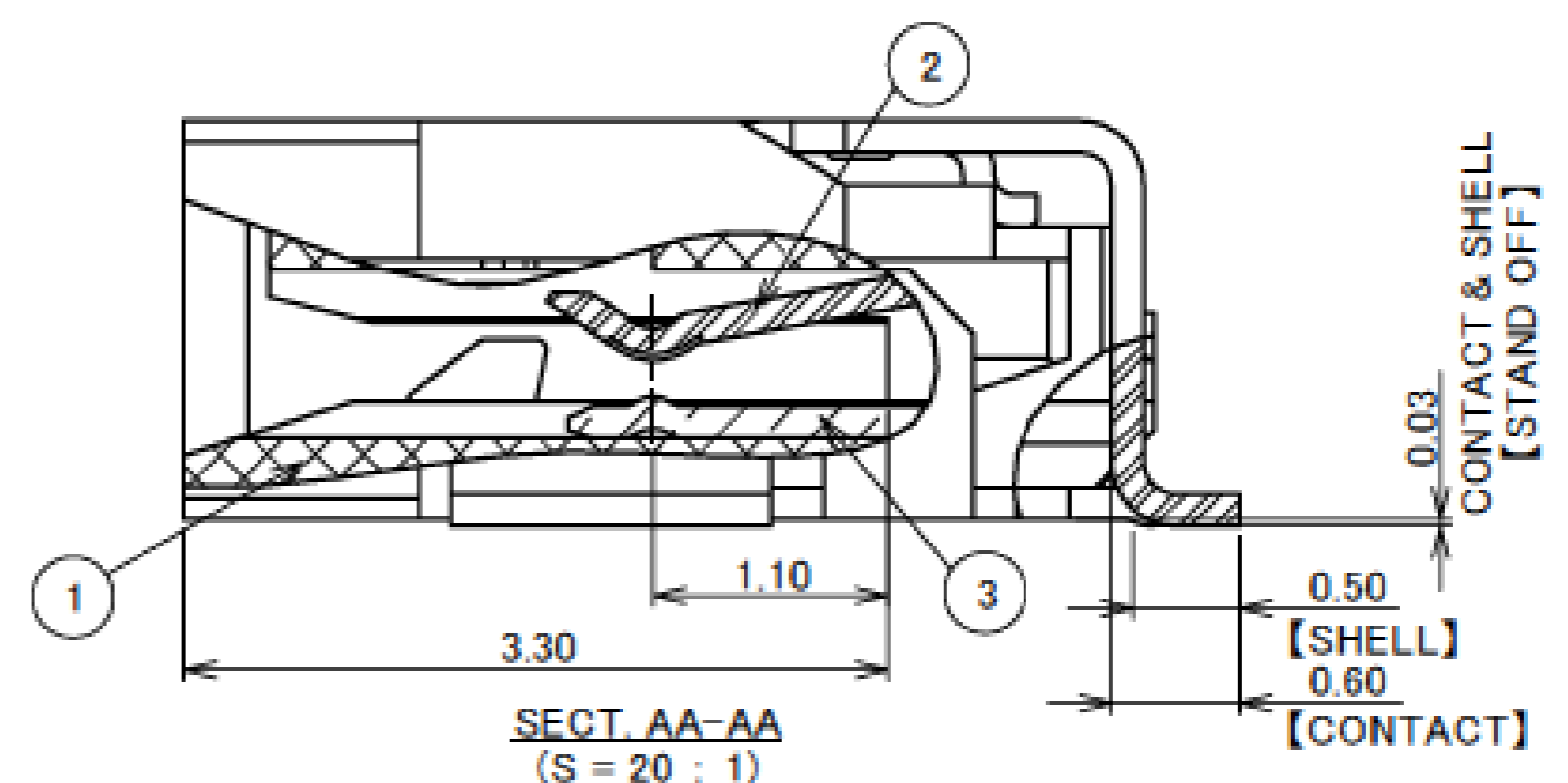
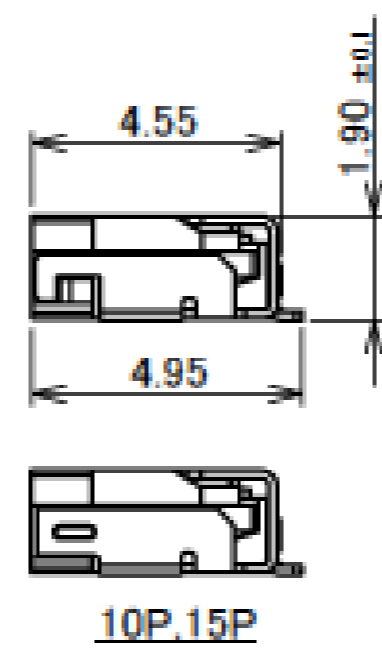
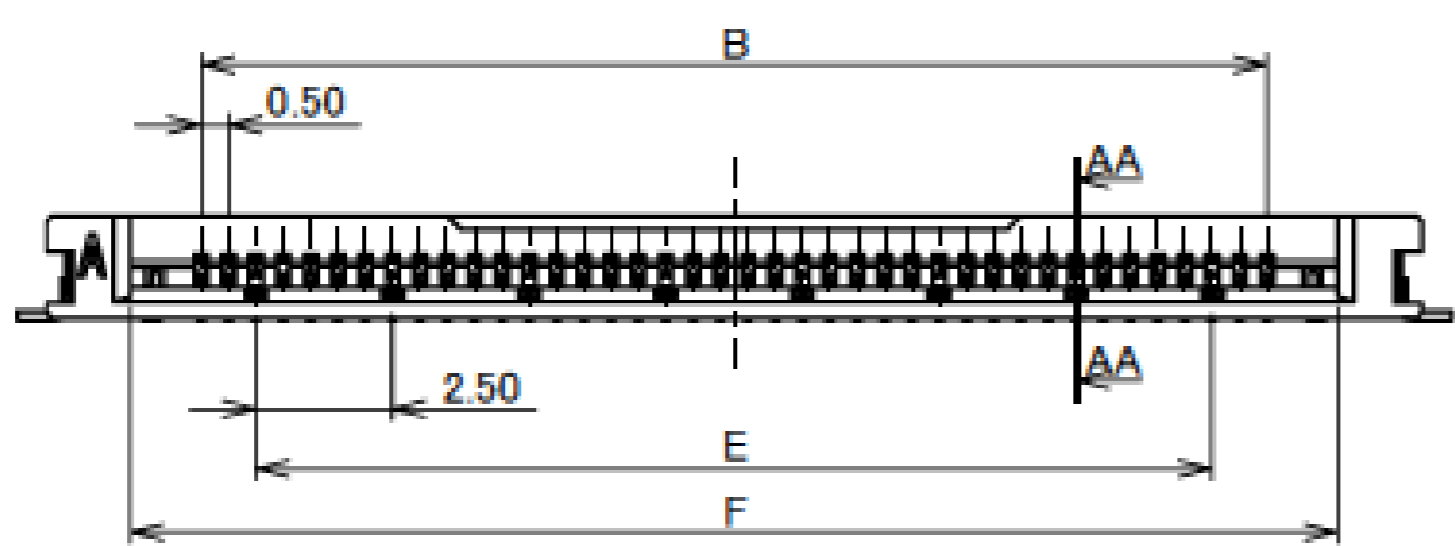
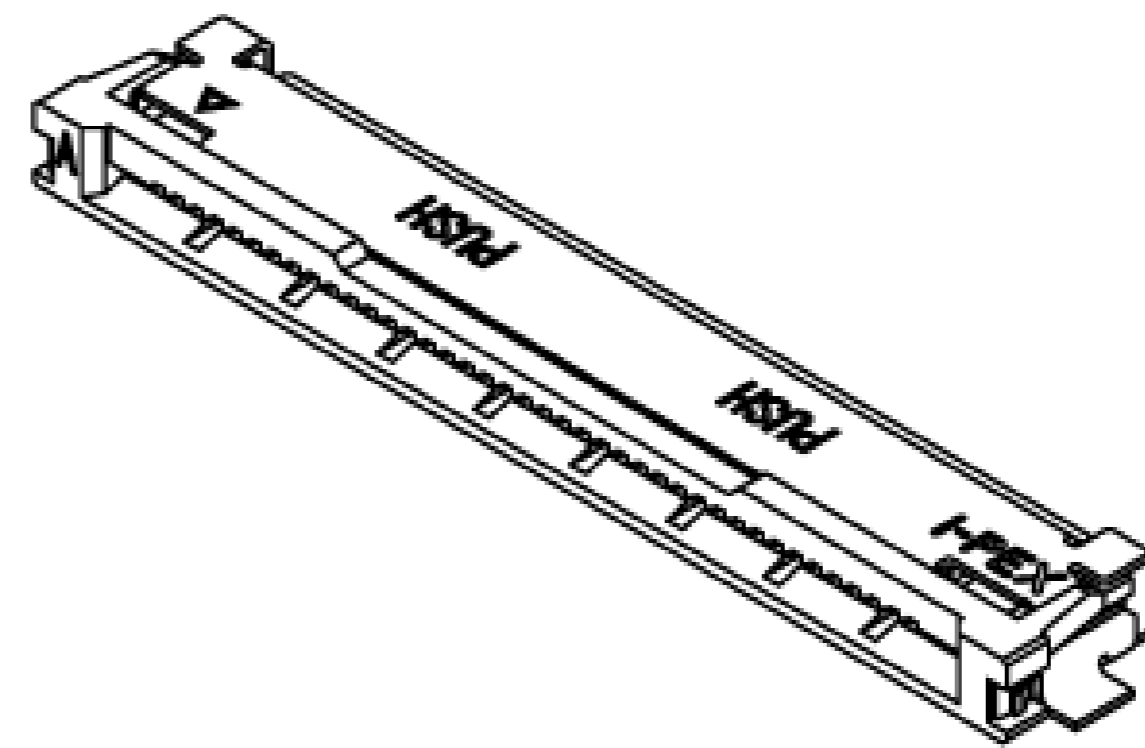
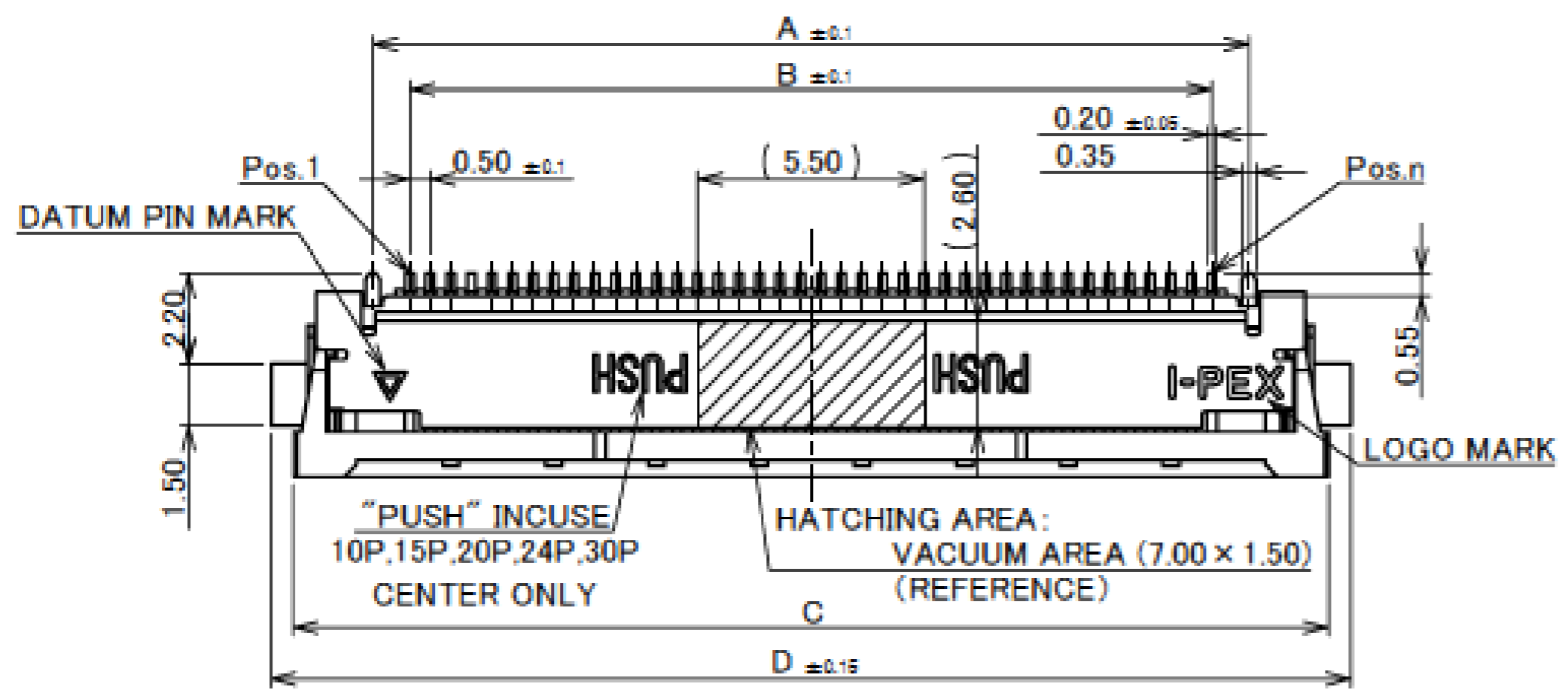
	EVAFLEX® 5-HD
Height (mm)	2.00 +/- 02
Reference Performance	USB4 (20 Gbps)
Special Feature	360度フルシールドと多点グラウンド接点によるEMI対策設計



# Component Parts Detail

## Connector Assembly

Recommended P/N		20535-0**E-02					
PART No.	POS.	A	B	C	D	E	F
20535-010E-02	10P	6.30	4.50	10.17	11.25	2.50	7.10
20535-015E-02	15P	8.80	7.00	12.67	13.75	5.00	9.60
20535-020E-02	20P	11.30	9.50	15.17	16.25	7.50	12.10
20535-024E-02	24P	13.30	11.50	17.17	18.25	7.50	14.10
20535-030E-02	30P	16.30	14.50	20.17	21.25	12.50	17.10
20535-040E-02	40P	21.30	19.50	25.17	26.25	17.50	22.10

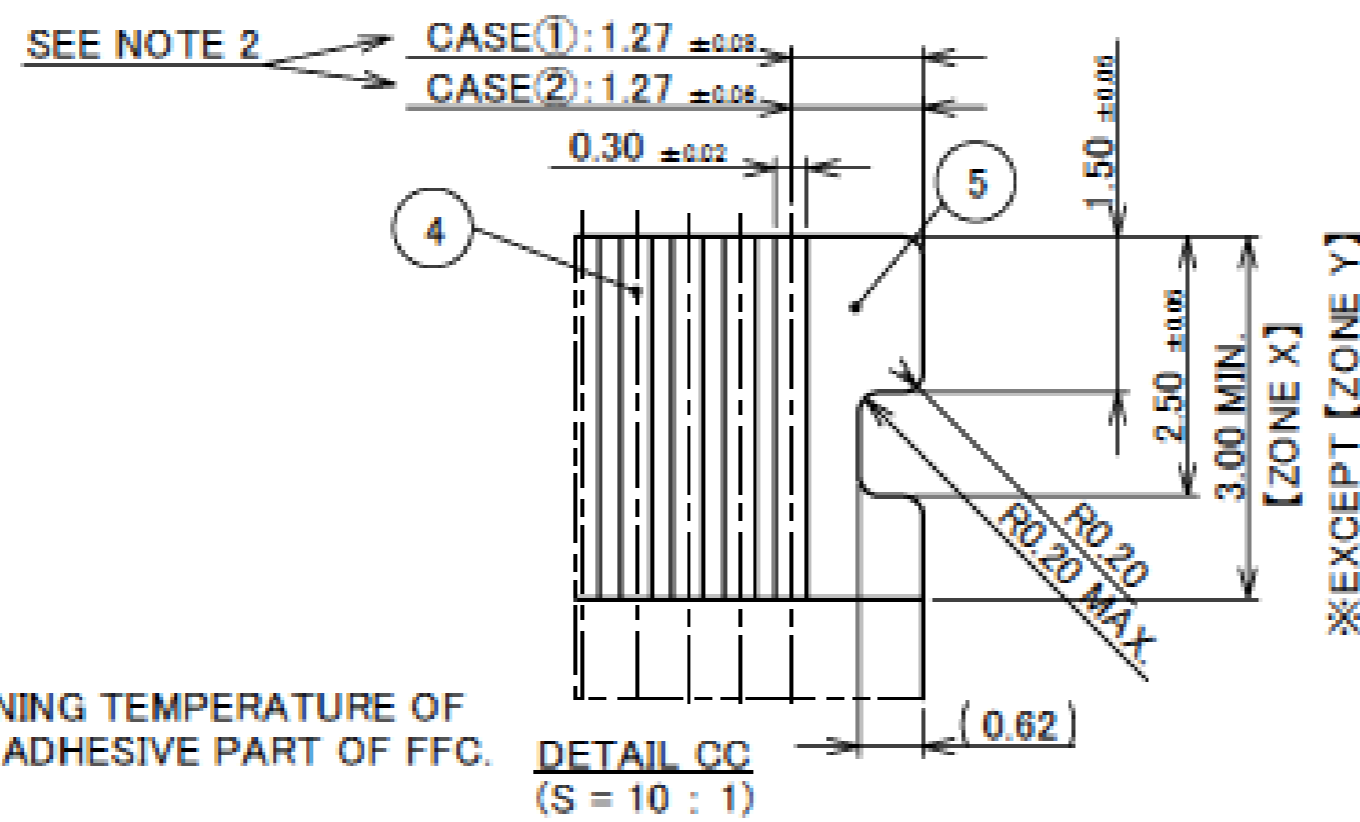
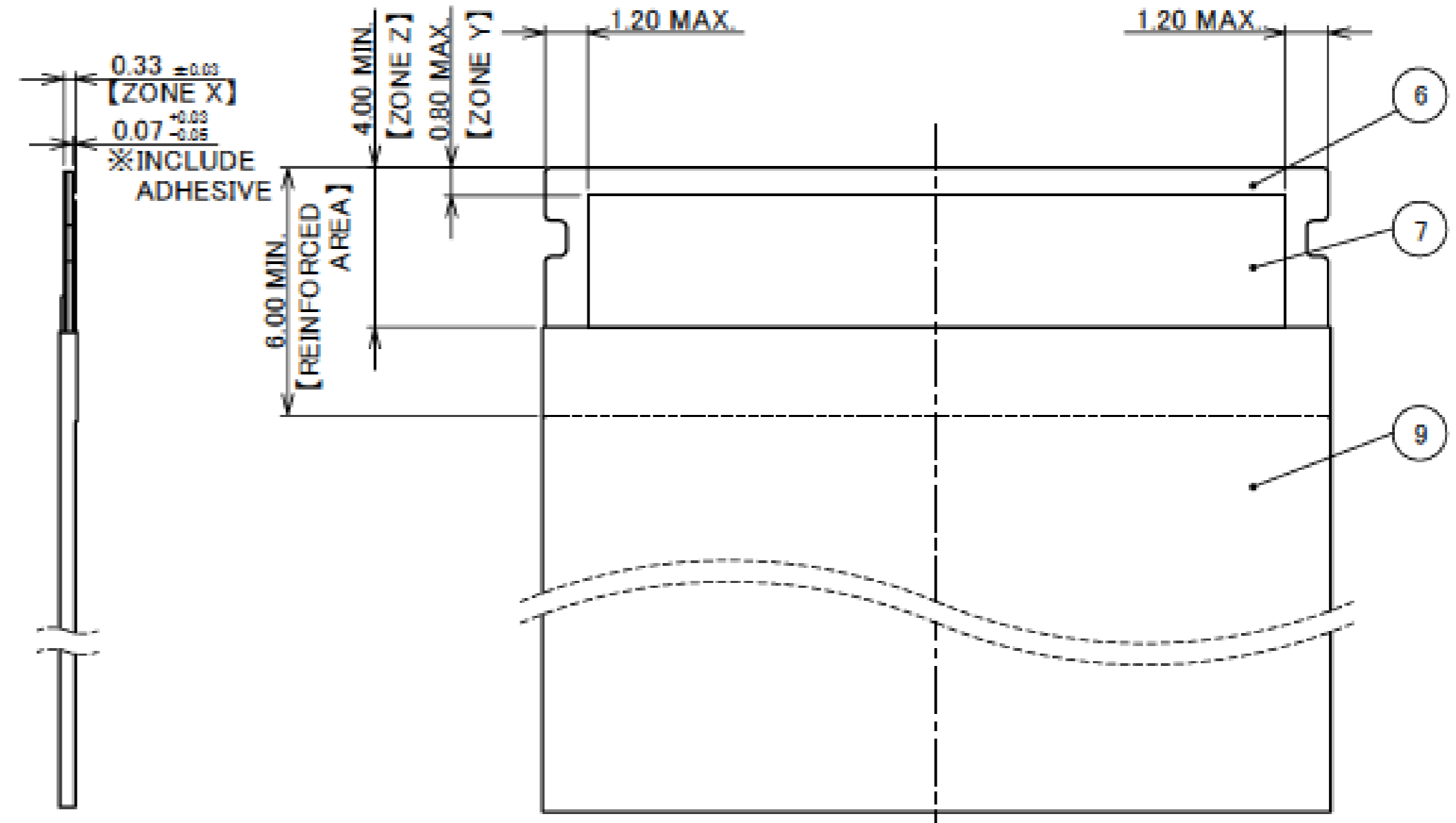
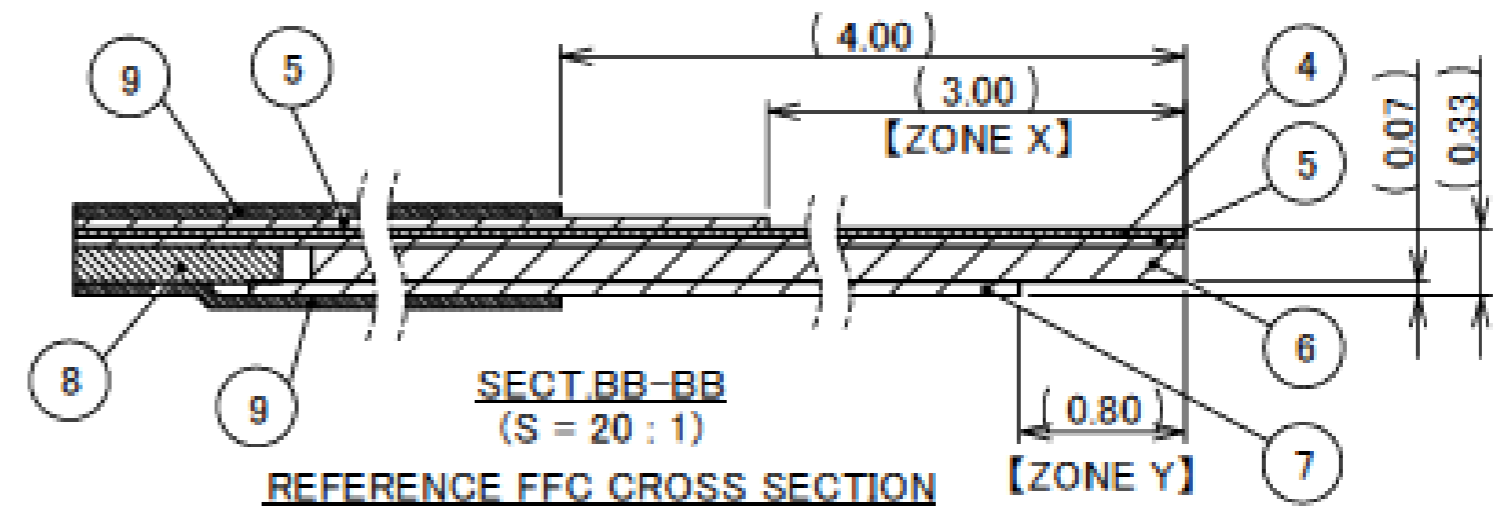
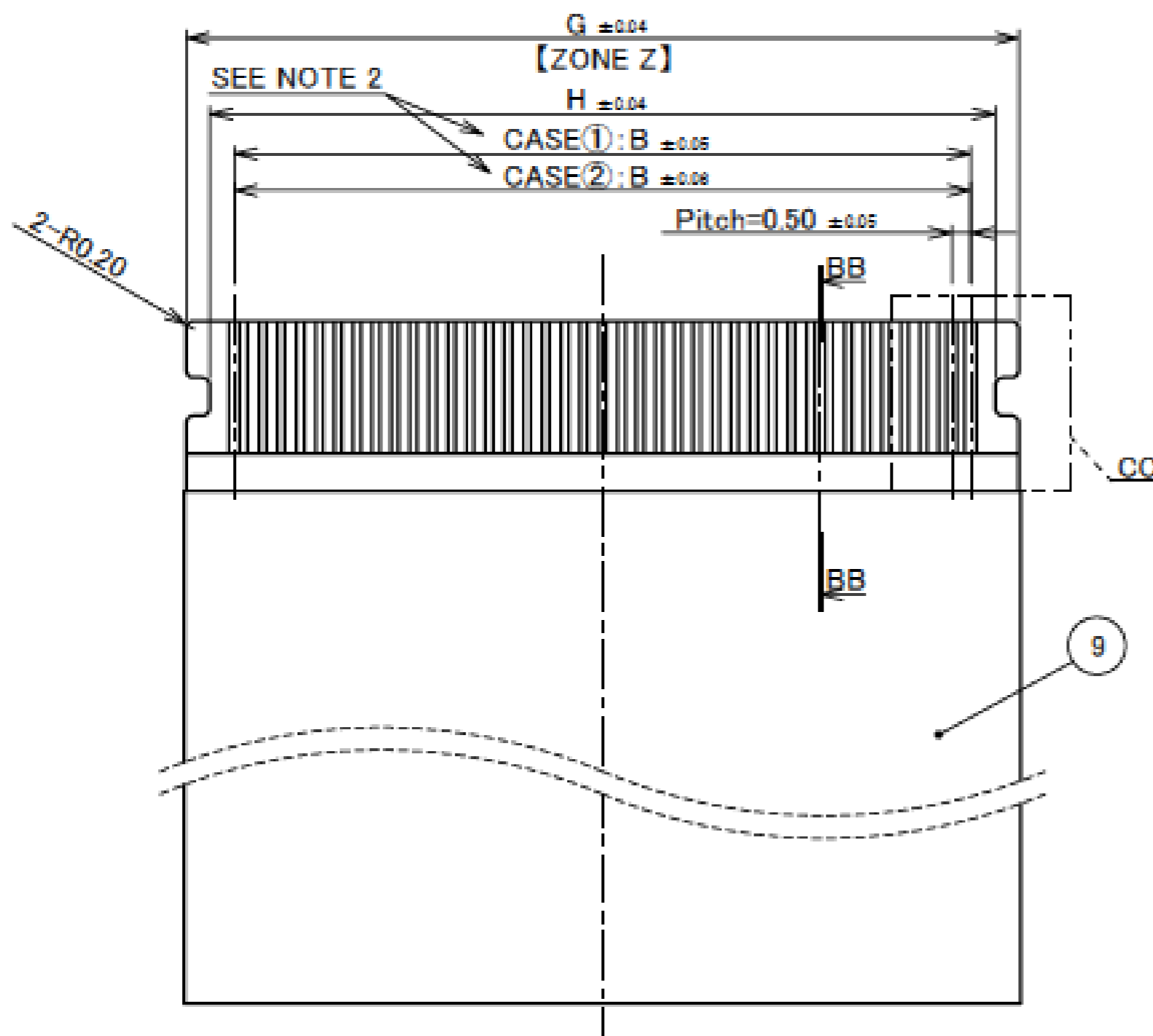


NO.	DISCRPTION	MATERIAL	FINISH . REMARKS
3	SHELL	PHOSPHOR BRONZE	Sn 1.00 μm MIN. OVER Ni 1.00 μm MIN. PLATING
2	CONTACT	PHOSPHOR BRONZE	Au OVER Ni PLATING CONTACT AREA: Au 0.03 μm MIN. OVER Ni 1.00 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK

# Connector Assembly

Recommended P/N		20535-0**E-02			
PART No.	POS.	B	G	H	
20535-010E-02	10P	4.50	7.04	5.80	
20535-015E-02	15P	7.00	9.54	8.30	
20535-020E-02	20P	9.50	12.04	10.80	
20535-024E-02	24P	11.50	14.04	12.80	
20535-030E-02	30P	14.50	17.04	15.80	
20535-040E-02	40P	19.50	22.04	20.80	

## RECOMMENDED FFC DIMENSION



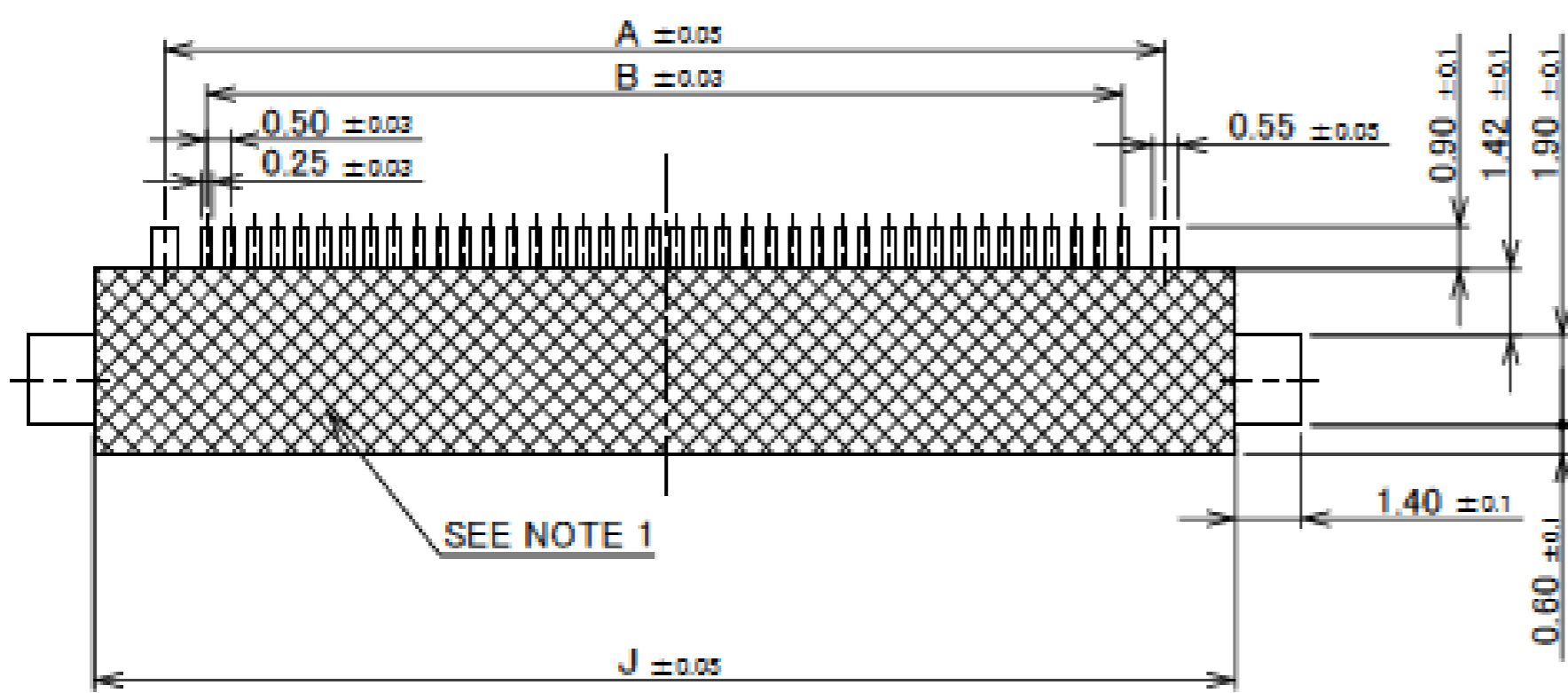
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
9	SHIELD TAPE	METALIC FILM	-
8	INTERLAYER	ARBITRARY	-
7	GROUND PLATE	METARIC FILM	POLISH or HALF POLISH Sn PLATING
6	REINFORCED TAPE	ARBITRARY	-
5	INSULATION FILM	ARBITRARY	-
4	CONDUCTOR	COPPER ALLOY	CONTACT AREA: Au 0.05 μm MIN. OVER Ni 0.5 μm MIN.

### NOTES

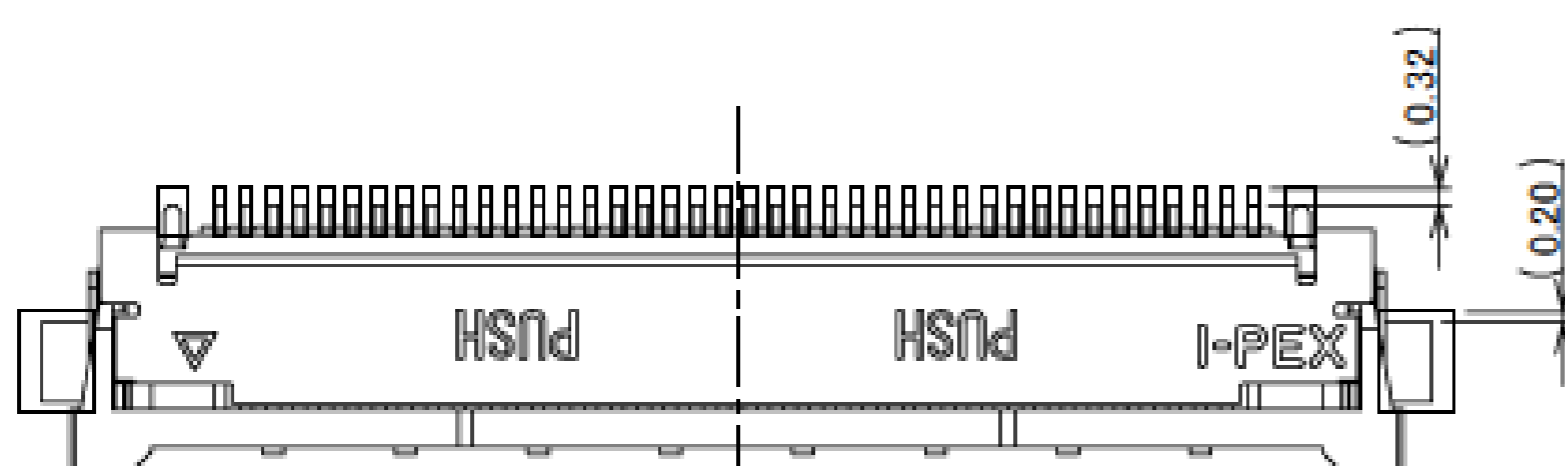
1. DIFFERENTIAL IMPEDANCE : 100Ω
2. MANUFACTURE CASE(1) or CASE(2)
3. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.

Rev.14

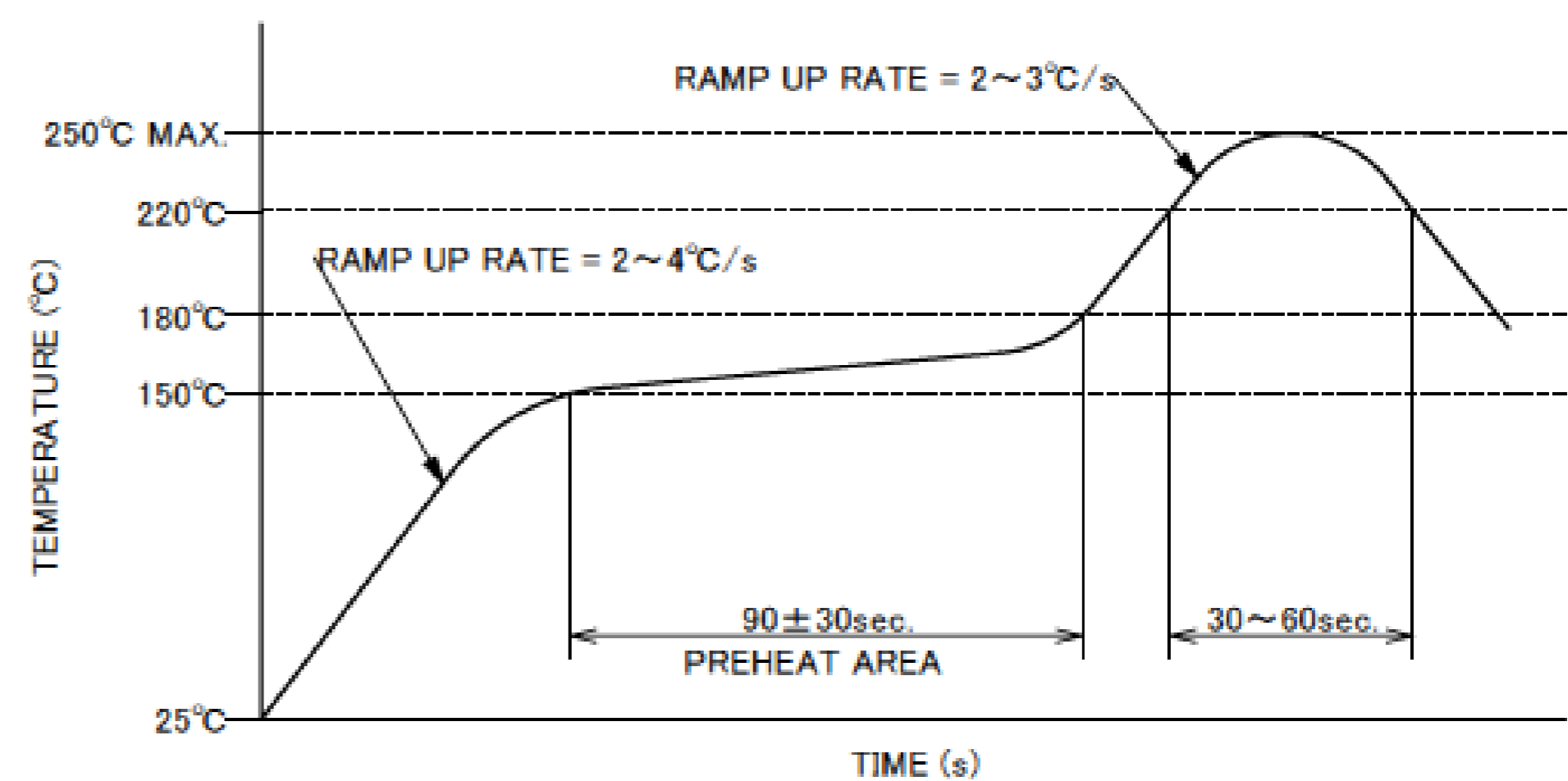
Recommended P/N		20535-0**E-02		
PART No.	POS.	A	B	J
20535-010E-02	10P	6.30	4.50	9.30
20535-015E-02	15P	8.80	7.00	11.80
20535-020E-02	20P	11.30	9.50	14.30
20535-024E-02	24P	13.30	11.50	16.30
20535-030E-02	30P	16.30	14.50	19.30
20535-040E-02	40P	21.30	19.50	24.30



RECOMMENDED PCB & METALMASK LAYOUT  
METALMASK THICKNESS: t=0.12



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE  
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

### NOTE

1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.

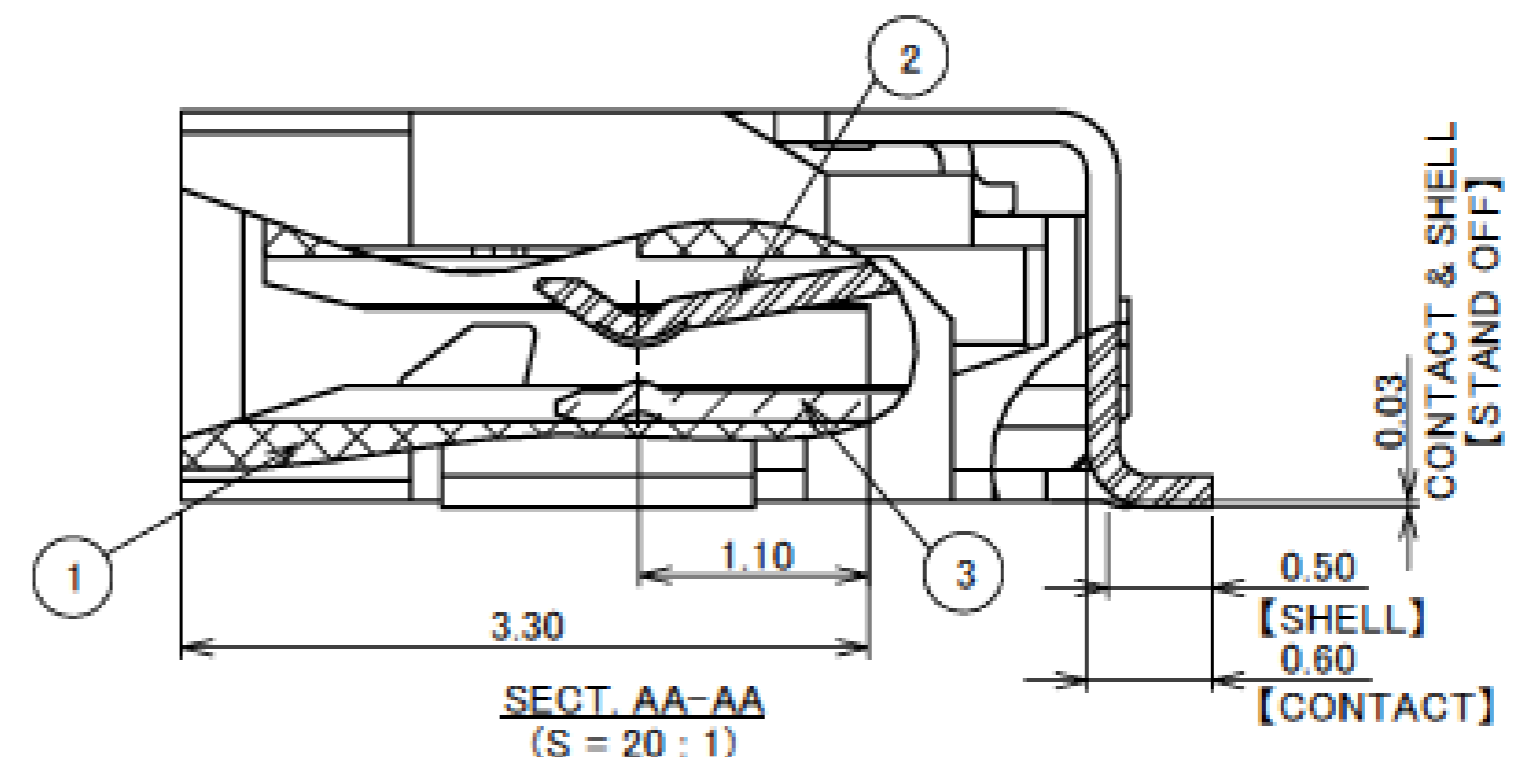
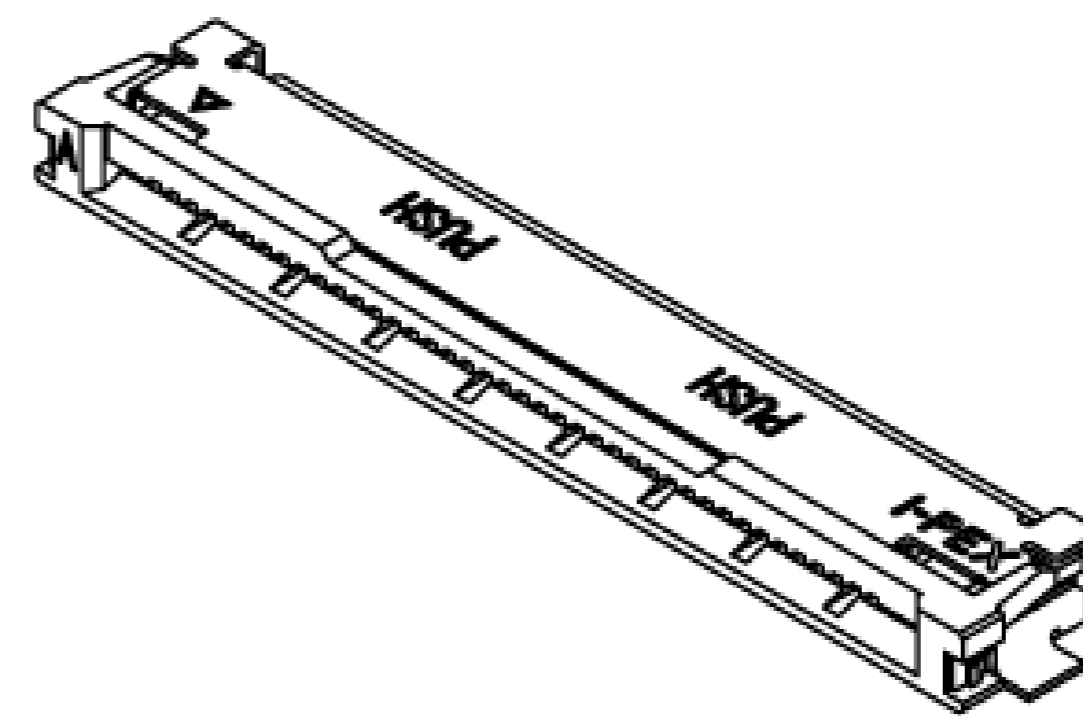
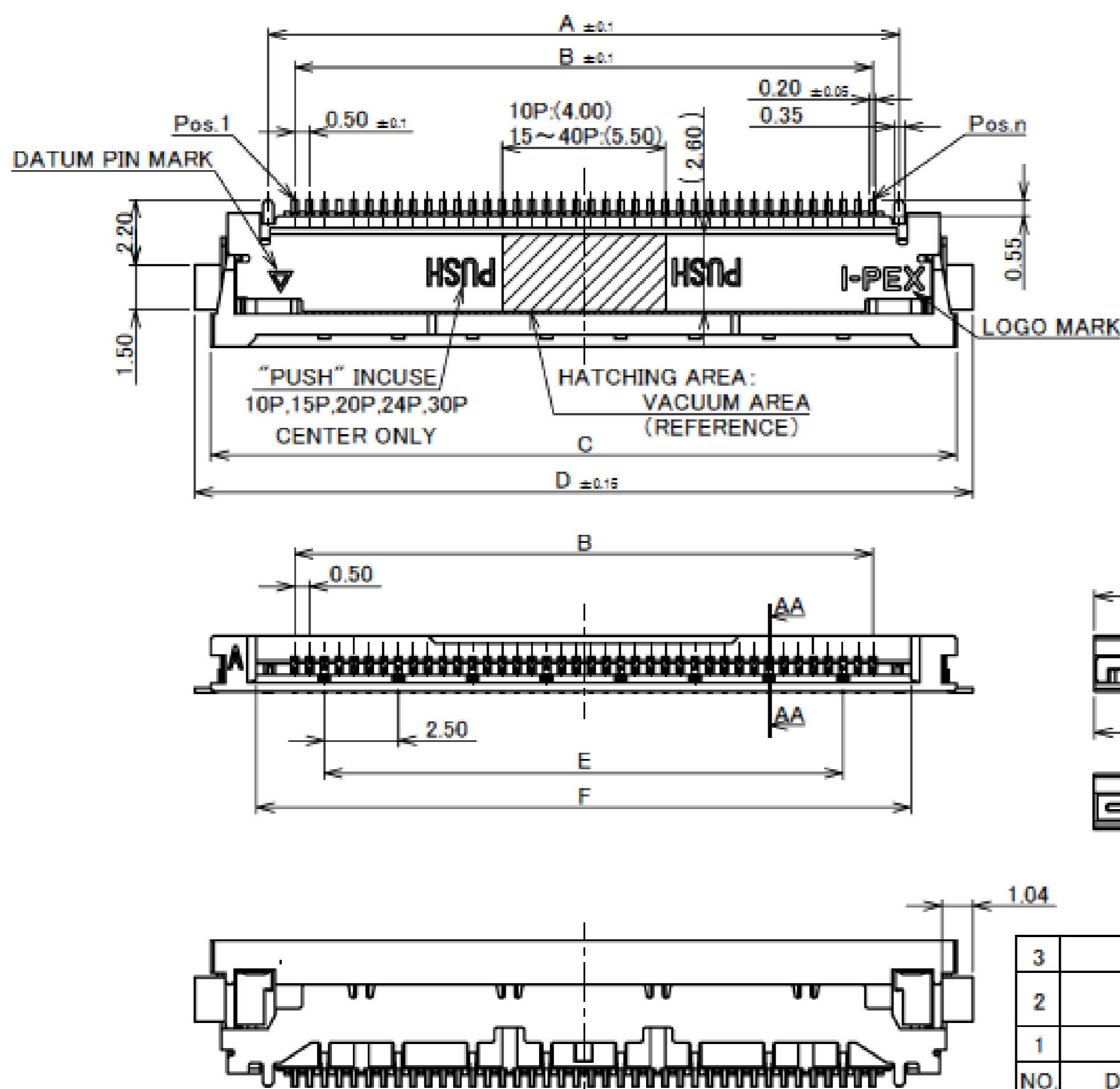
Rev.14

# Connector Assembly

ITEMS	SPECIFICATION
RATING VOLTAGE	200V AC/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR CONTACT)	0.3A AC/DC (PER CONTACT PIN) IN CASE OF APPLYING 0.5A PER CONTACT PIN, THE TOTAL CURRENT OF THE WHOLE CONNECTOR SHALL BE 15.0A OR LOWER.
OPERATING TEMPERATURE	233~358K(-40°C~+85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 60mohm MAX. / AFTER TEST : $\triangle$ 40mohm MAX.
INSULATION RESISTANCE	INITIAL : 100Mohm MIN. / AFTER TEST : 100Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	30 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	10P : 6.0N MAX. 15P : 9.0N MAX. 20P : 12.0N MAX. 24P : 14.4N MAX. 30P : 18.0N MAX. 40P : 24.0N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10P : 1.0N MIN. 15P : 1.5N MIN. 20P : 2.0N MIN. 24P : 2.4N MIN. 30P : 3.0N MIN. 40P : 4.0N MIN.
COPLANARITY	0.10 MAX.
PRODUCT SPECIFICATION	PRS-1670
TEST REPORT	TR-12108
PACKING STANDARD	300-997
INSTRUCTION MANUAL	HIM-12003
APPEARANCE CRITERIA No.	QLS-A***

Rev.14

Recommended P/N		20720-0**E-02					
PART NO.	POS.	A	B	C	D	E	F
20720-010E-02	10P	6.30	4.50	10.17	11.25	2.50	7.10
20720-015E-02	15P	8.80	7.00	12.67	13.75	5.00	9.60
20720-020E-02	20P	11.30	9.50	15.17	16.25	7.50	12.10
20720-024E-02	24P	13.30	11.50	17.17	18.25	7.50	14.10
20720-030E-02	30P	16.30	14.50	20.17	21.25	12.50	17.10
20720-040E-02	40P	21.30	19.50	25.17	26.25	17.50	22.10



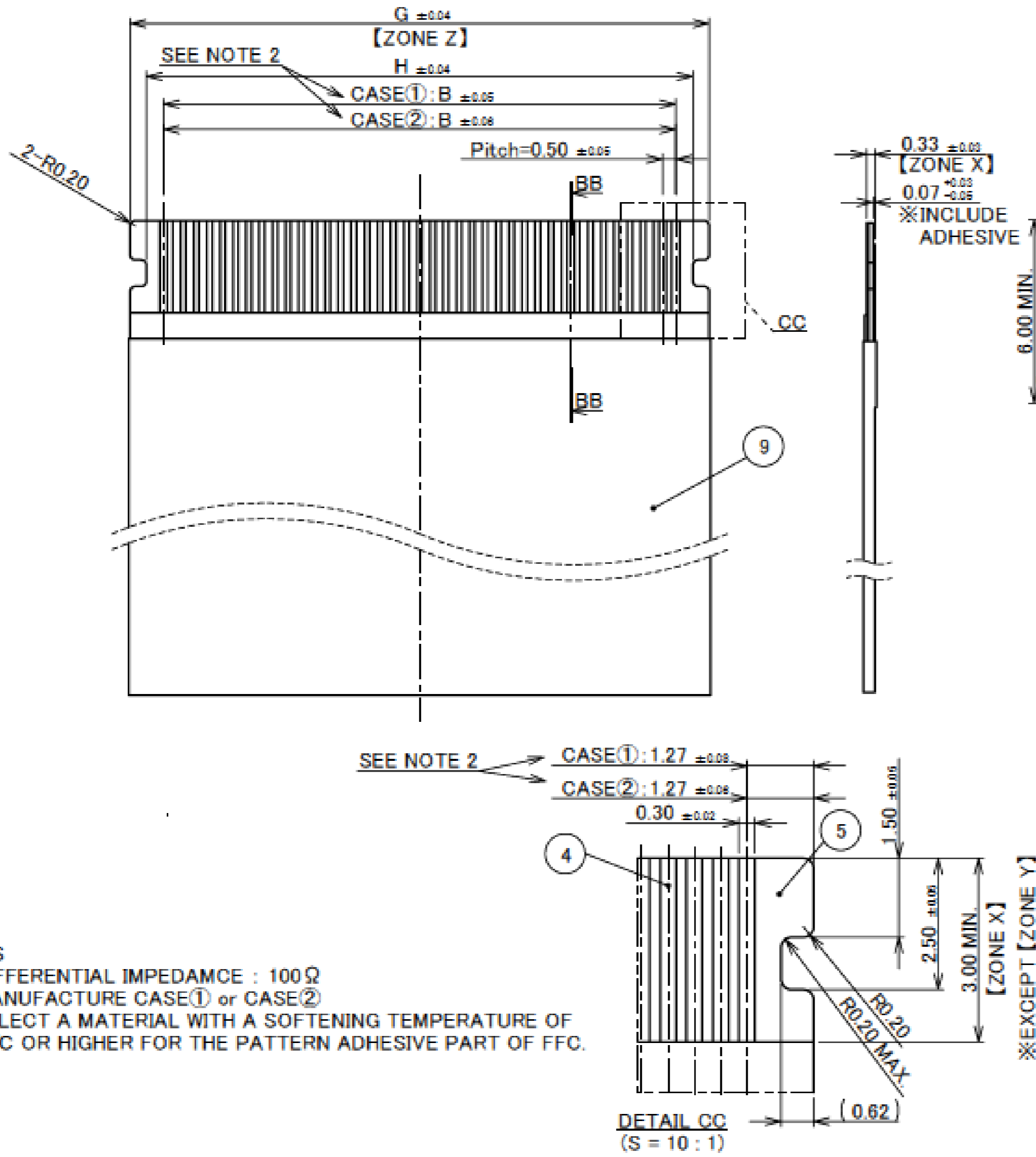
NO.	DISCRIPTION	MATERIAL	FINISH . REMARKS
3	SHELL	PHOSPHOR BRONZE	Sn OVER Ni PLATING
2	CONTACT	CORSON ALLOY	Au OVER Ni PLATING CONTACT AREA: Au 0.03 $\mu$ m MIN. OVER Ni 1.00 $\mu$ m MIN.
1	HOUSING	LCP	UL94V-0, BLACK

Rev.7

# Connector Assembly

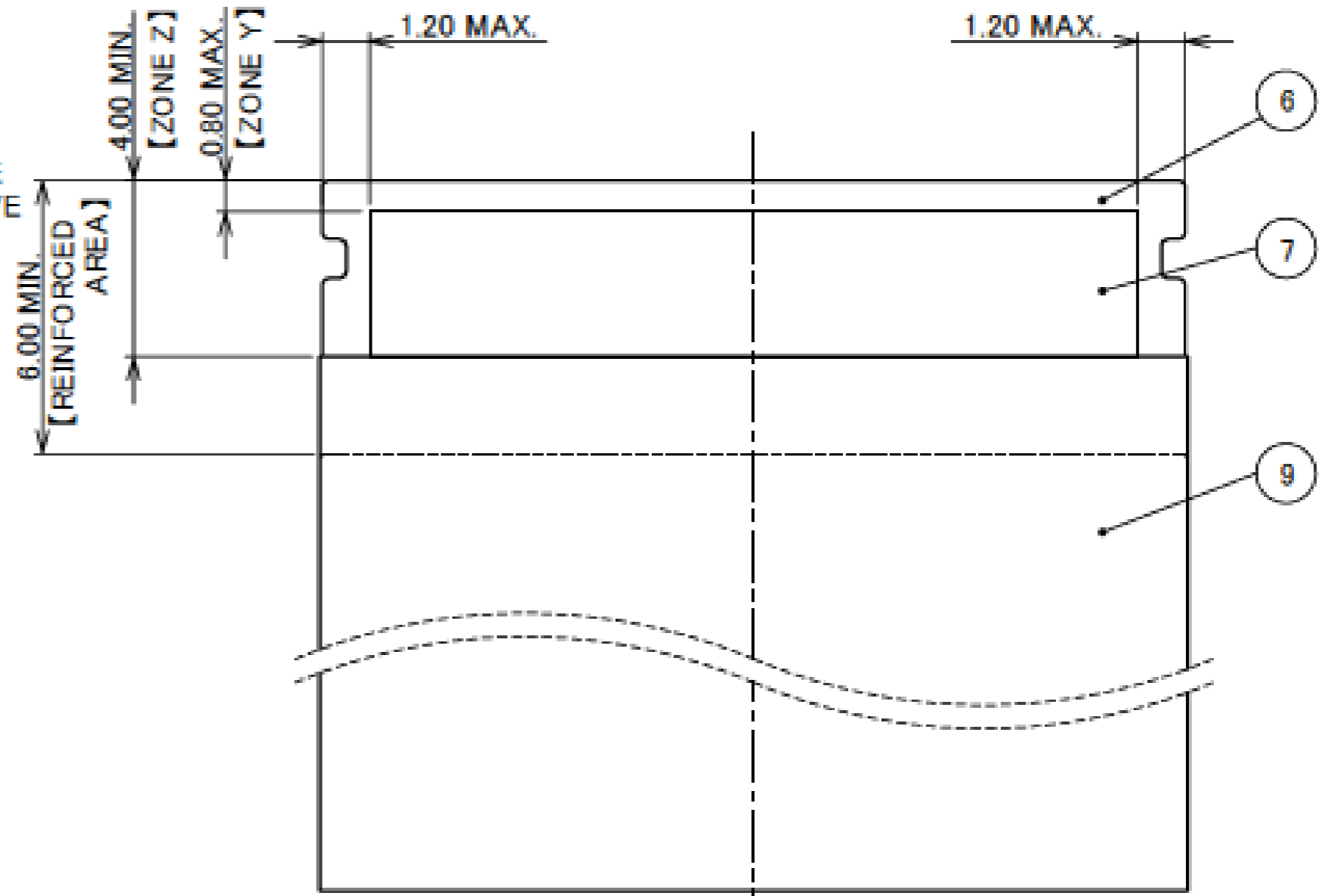
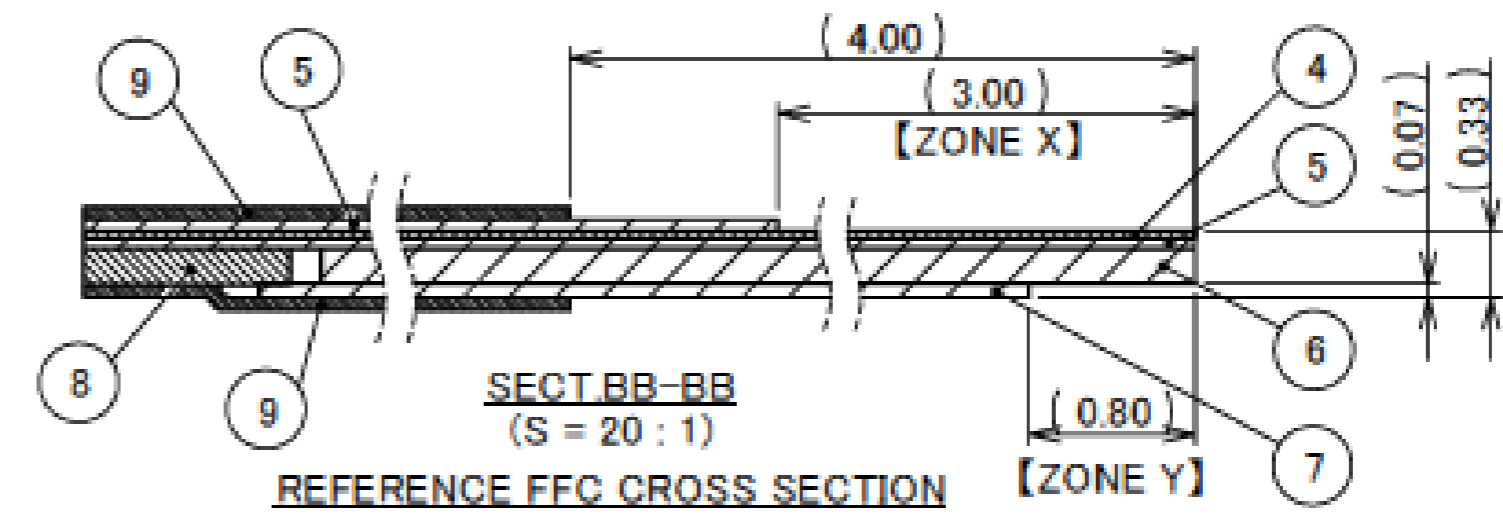
Recommended P/N		20720-0**E-02		
FOR	POS.	B	G	H
20720-010E-02	10P	4.50	7.04	5.80
20720-015E-02	15P	7.00	9.54	8.30
20720-020E-02	20P	9.50	12.04	10.80
20720-024E-02	24P	11.50	14.04	12.80
20720-030E-02	30P	14.50	17.04	15.80
20720-040E-02	40P	19.50	22.04	20.80

## RECOMMENDED FFC DIMENSION



### NOTES

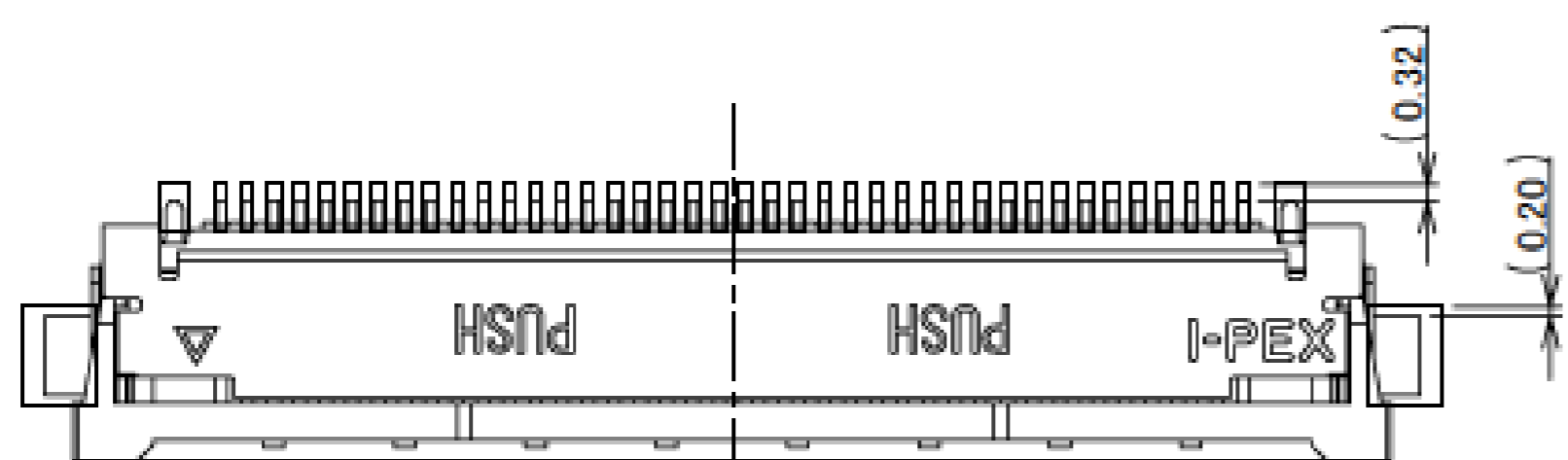
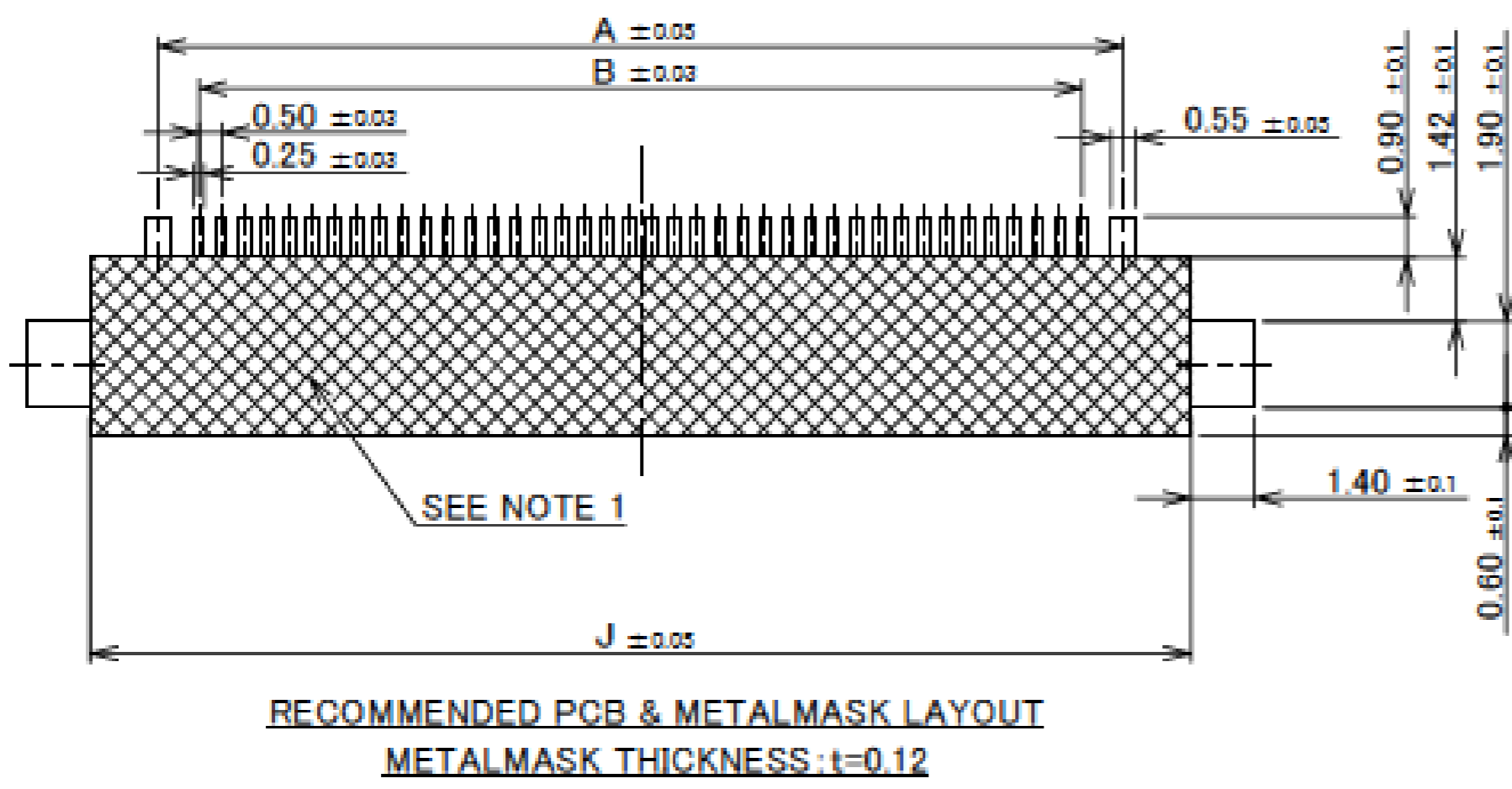
1. DIFFERENTIAL IMPEDANCE : 100Ω
2. MANUFACTURE CASE① or CASE②
3. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.



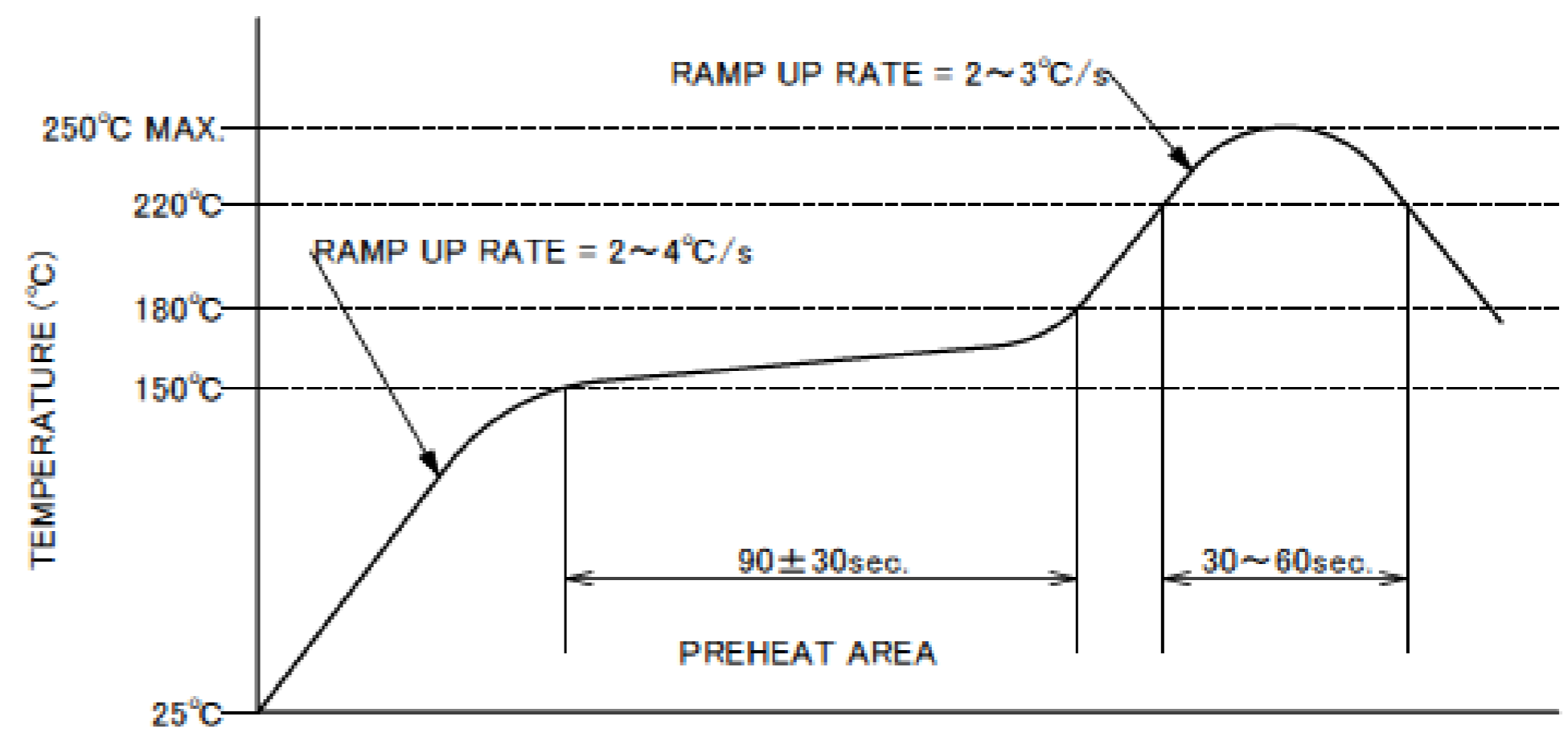
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
9	SHIELD TAPE	METALIC FILM	-
8	INTERLAYER	ARBITRARY	-
7	GROUND PLATE	METARIC FILM	POLISH or HALF POLISH Sn PLATING
6	REINFORCED TAPE	ARBITRARY	-
5	INSULATION FILM	ARBITRARY	-
4	CONDUCTOR	COPPER ALLOY	CONTACT AREA: Au 0.05 μm MIN. OVER Ni 0.5 μm MIN.

Rev.7

Recommended P/N		20720-0**E-02		
PART NO.	POS.	A	B	J
20720-010E-02	10P	6.30	4.50	9.30
20720-015E-02	15P	8.80	7.00	11.80
20720-020E-02	20P	11.30	9.50	14.30
20720-024E-02	24P	13.30	11.50	16.30
20720-030E-02	30P	16.30	14.50	19.30
20720-040E-02	40P	21.30	19.50	24.30



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE  
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

### NOTE

1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.

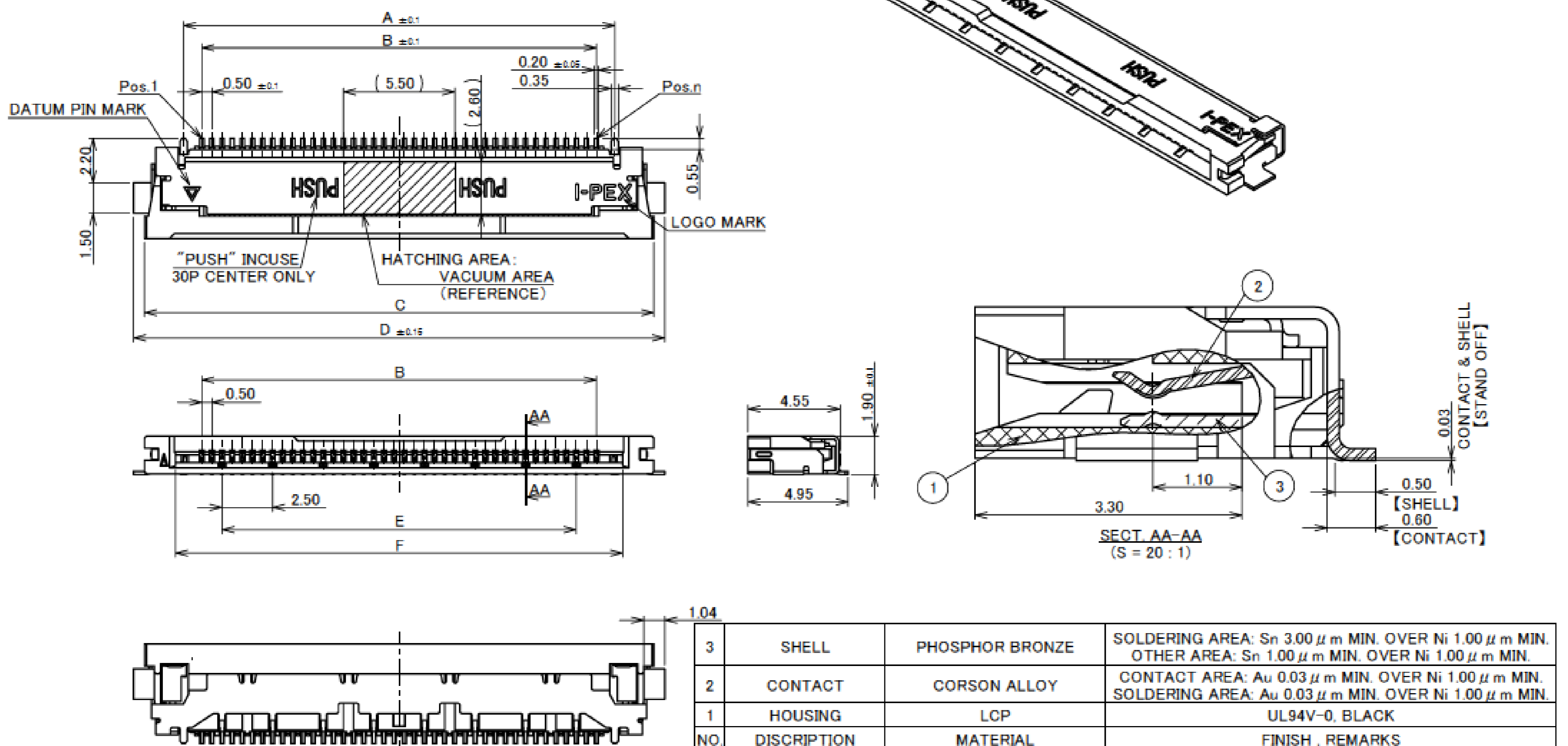
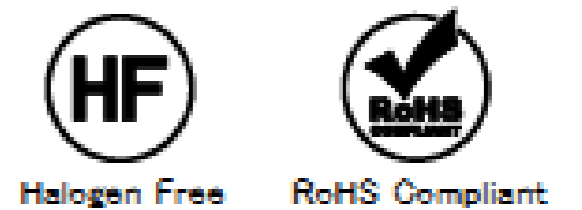
Rev.7

# Connector Assembly

ITEMS	SPECIFICATION
RATING VOLTAGE	200V AC/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR CONTACT)	0.3A AC/DC (PER CONTACT PIN) IN CASE OF APPLYING 0.5A PER CONTACT PIN, THE TOTAL CURRENT OF THE WHOLE CONNECTOR SHALL BE 15.0A OR LOWER.
OPERATING TEMPERATURE	233~378K(-40°C~+105°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 60mohm MAX. / AFTER TEST : $\triangle$ 40mohm MAX.
INSULATION RESISTANCE	INITIAL : 100Mohm MIN. / AFTER TEST : 100Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	30 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	10P : 6.0N MAX. 15P : 9.0N MAX. 20P : 12.0N MAX. 24P : 14.4N MAX. 30P : 18.0N MAX. 40P : 24.0N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10P : 1.0N MIN. 15P : 1.5N MIN. 20P : 2.0N MIN. 24P : 2.4N MIN. 30P : 3.0N MIN. 40P : 4.0N MIN.
COPLANARITY	0.10 MAX.
PRODUCT SPECIFICATION	PRS-2224
TEST REPORT	TR-16039
PACKING STANDARD	300-997
INSTRUCTION MANUAL	HIM-12003
APPEARANCE CRITERIA No.	QLS-A***

Rev.7

Recommended P/N		20893-0**E-02					
PART NO.	POS.	A	B	C	D	E	F
20893-030E-02	30P	16.30	14.50	20.17	21.25	12.50	17.10
20893-040E-02	40P	21.30	19.50	25.17	26.25	17.50	22.10
20893-050E-02	50P	26.30	24.50	30.17	31.25	22.50	27.10

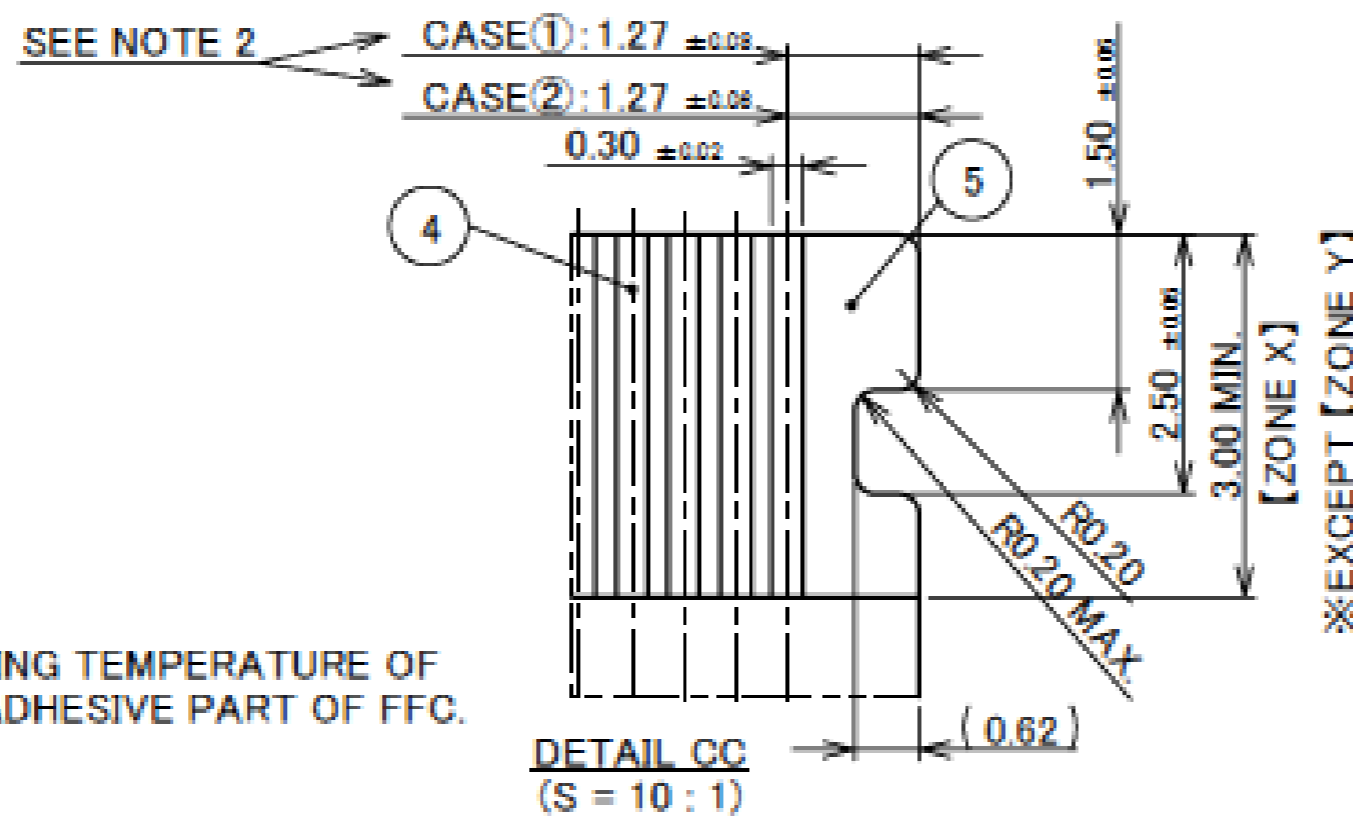
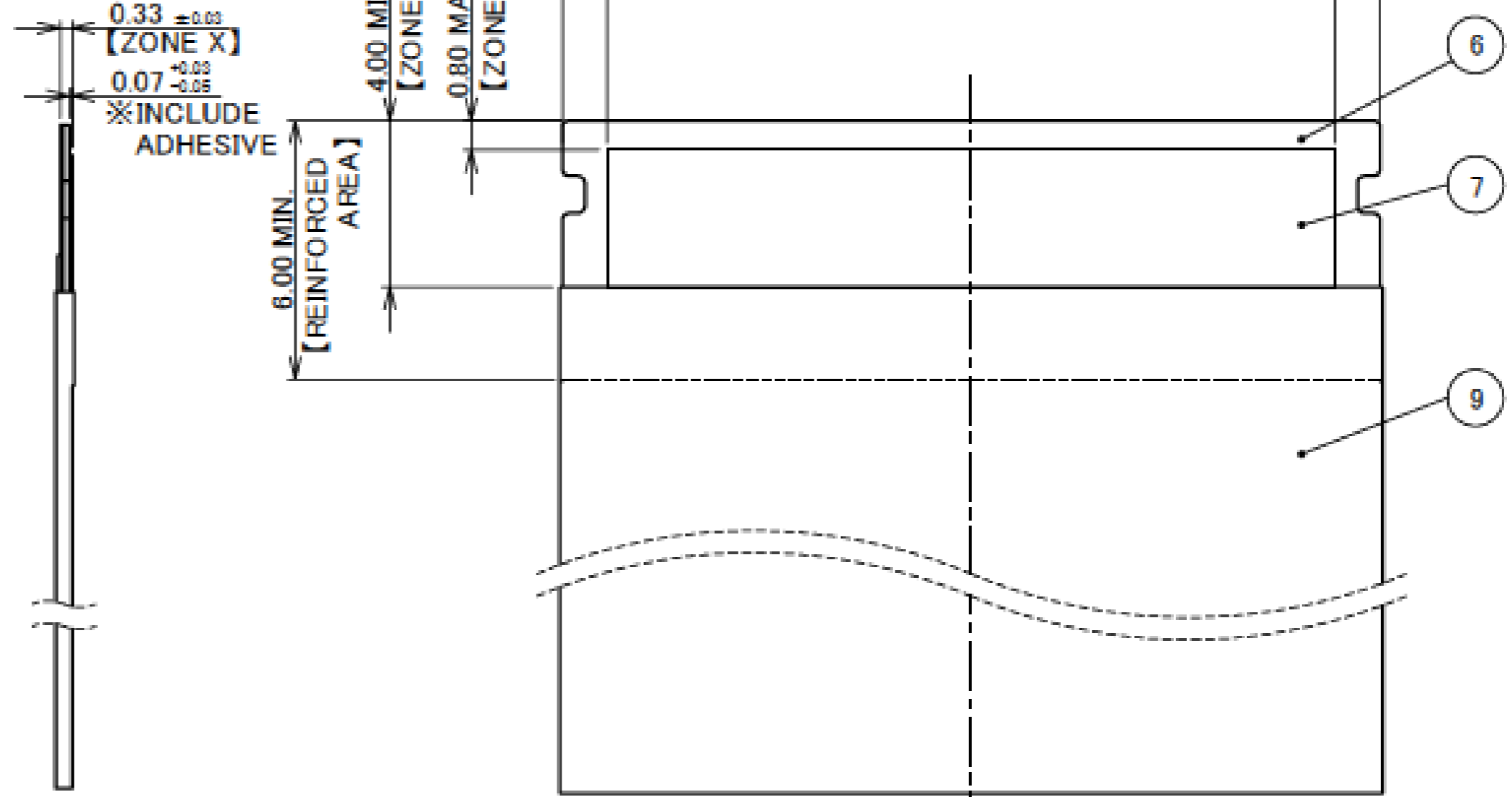
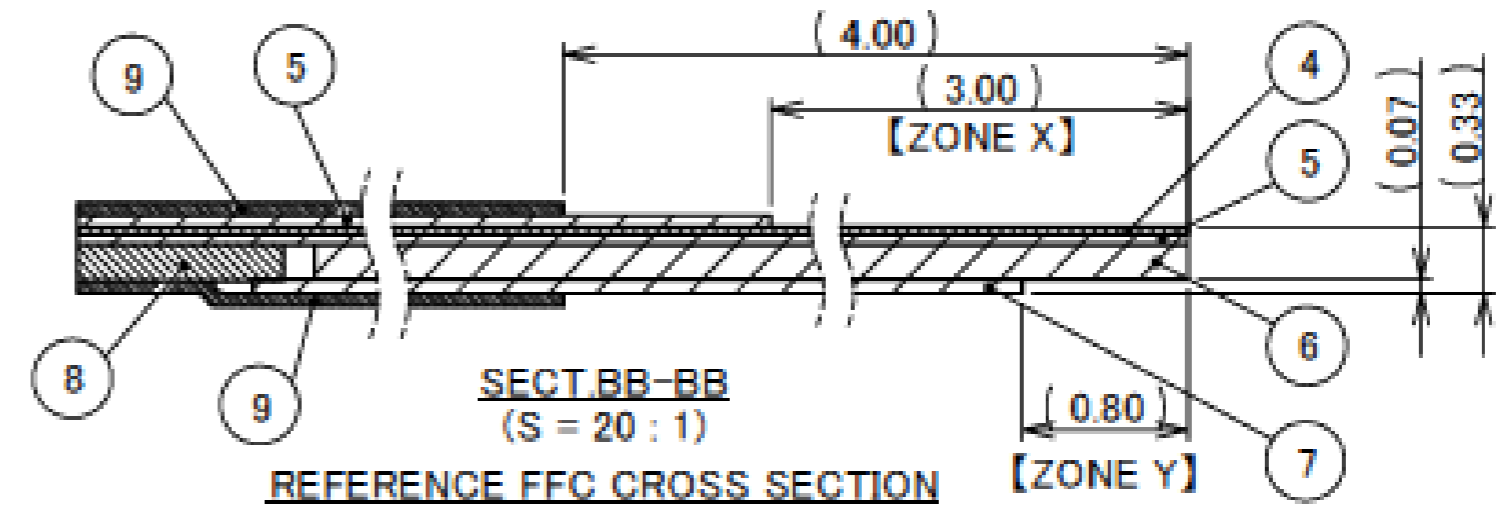
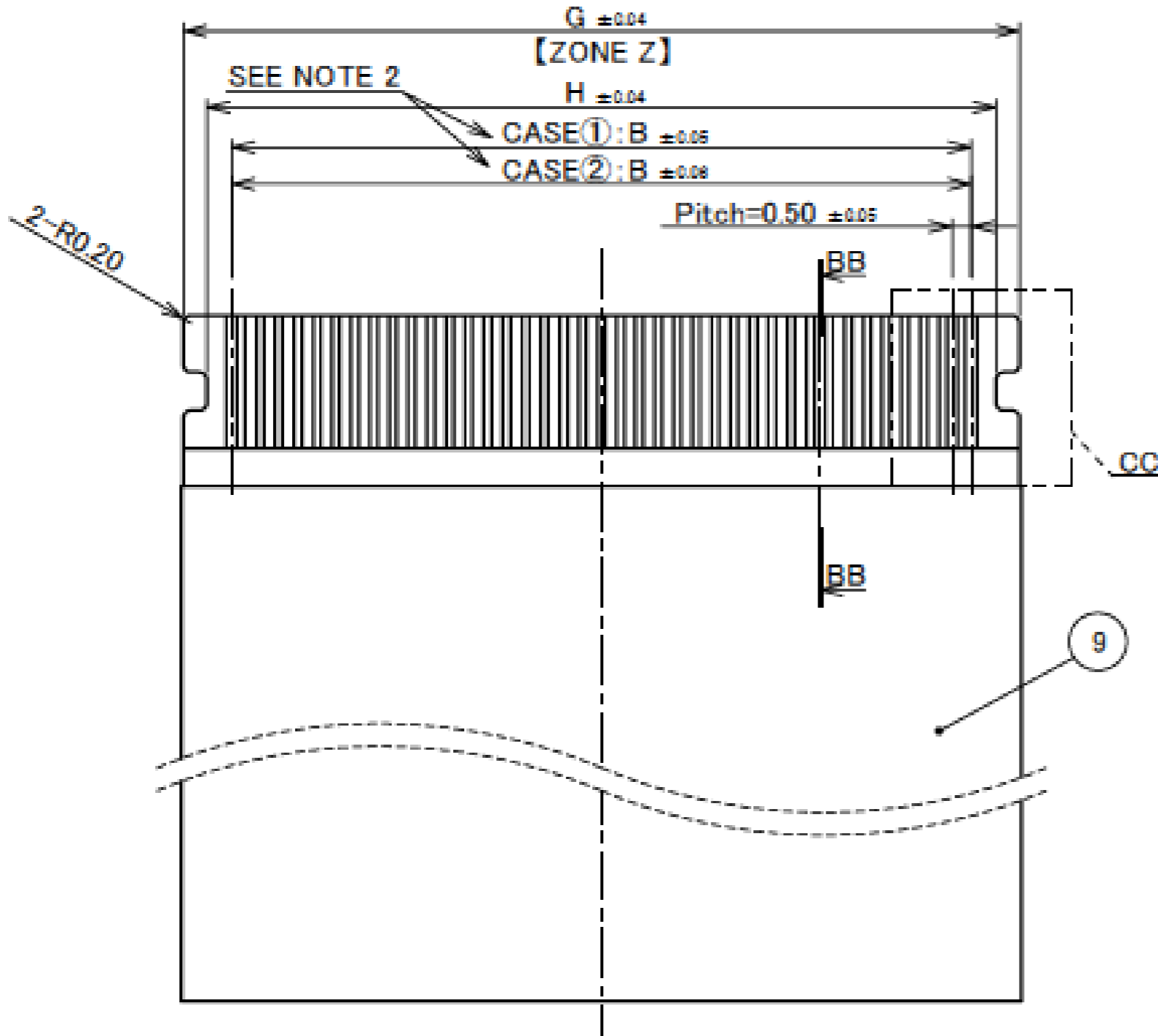


Rev.3

# Connector Assembly

Recommended P/N		20893-0**E-02		
FOR	POS.	B	G	H
20893-030E-02	30P	14.50	17.04	15.80
20893-040E-02	40P	19.50	22.04	20.80
20893-050E-02	50P	24.50	27.04	25.80

## RECOMMENDED FFC DIMENSION



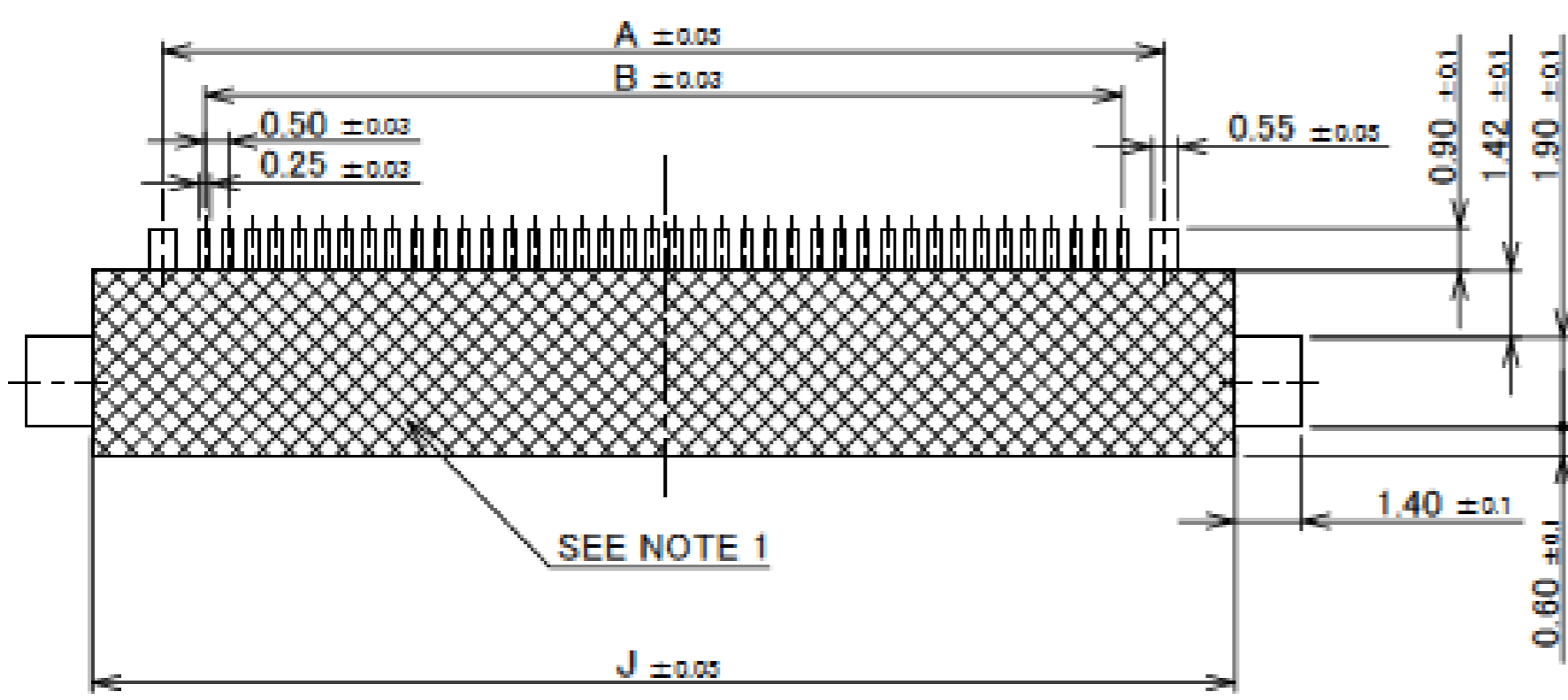
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
9	SHIELD TAPE	METALIC FILM	-
8	INTERLAYER	ARBITRARY	-
7	GROUND PLATE	METARIC FILM	POLISH or HALF POLISH Sn PLATING
6	REINFORCED TAPE	ARBITRARY	-
5	INSULATION FILM	ARBITRARY	-
4	CONDUCTOR	COPPER ALLOY	CONTACT AREA: Au 0.05 μm MIN. OVER Ni 0.5 μm MIN.

### NOTES

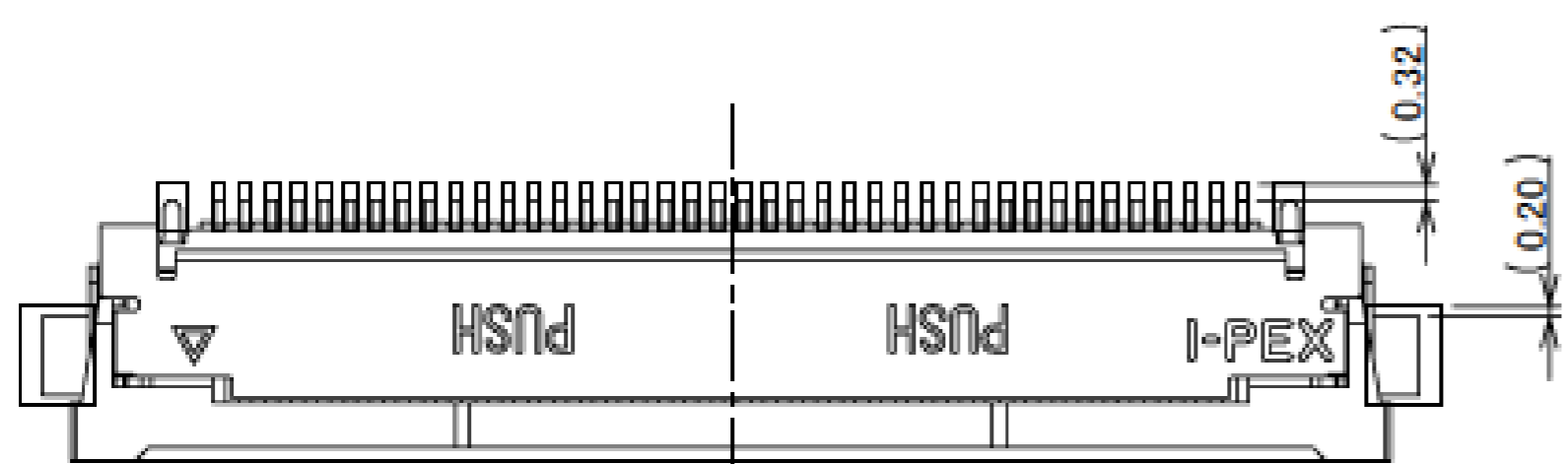
1. DIFFERENTIAL IMPEDANCE : 100 Ω
2. MANUFACTURE CASE(1) or CASE(2)
3. SELECT A MATERIAL WITH A SOFTENING TEMPERATURE OF 85°C OR HIGHER FOR THE PATTERN ADHESIVE PART OF FFC.

Rev.3

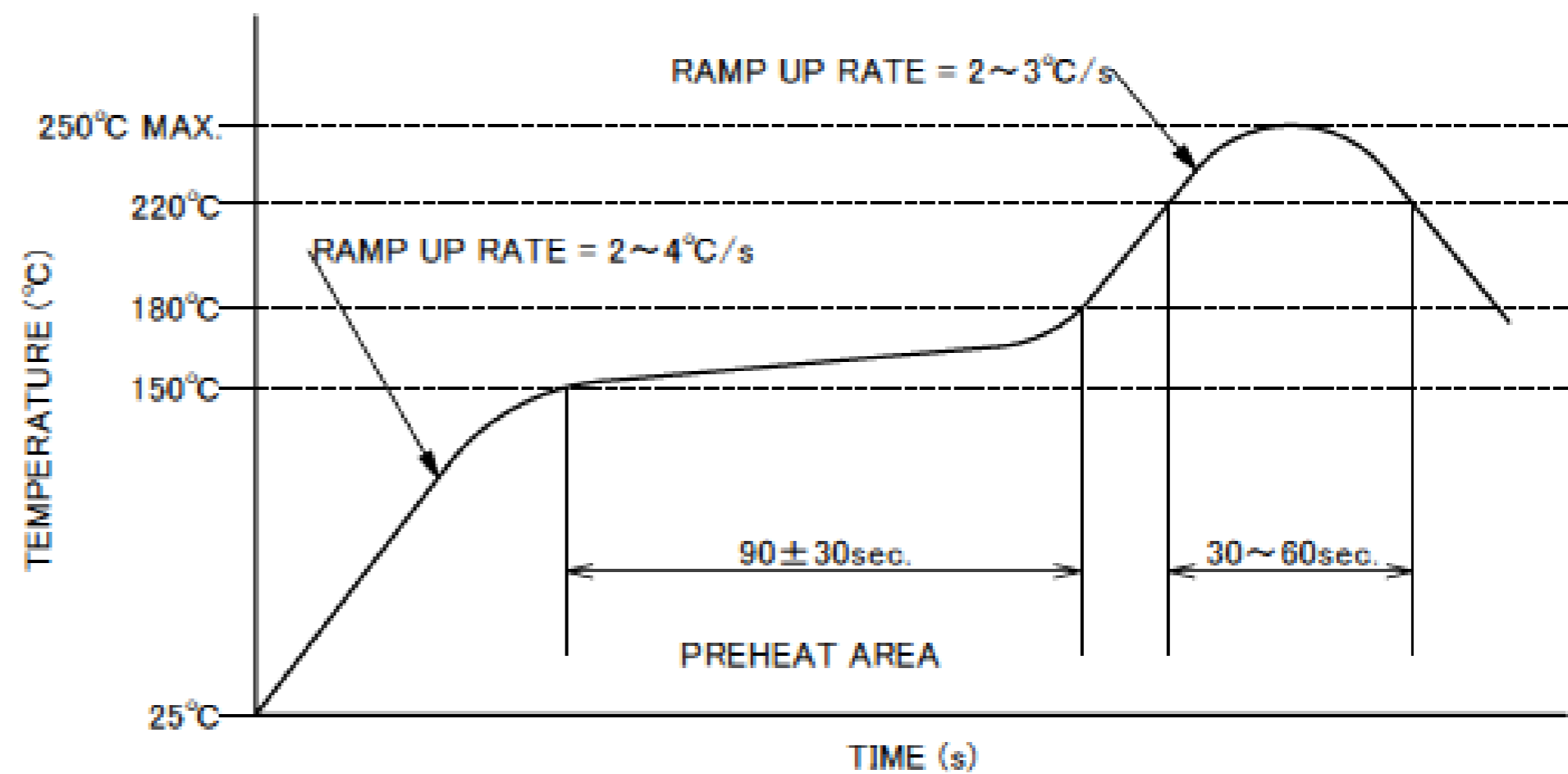
Recommended P/N		20893-0**E-02		
PART NO.	POS.	A	B	J
20893-030E-02	30P	16.30	14.50	19.30
20893-040E-02	40P	21.30	19.50	24.30
20893-050E-02	50P	26.30	24.50	29.30



RECOMMENDED PCB & METALMASK LAYOUT  
METAL MASK THICKNESS: t=0.12



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE  
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

### NOTE

1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.

Rev.3

## Connector Assembly

ITEMS	SPECIFICATION
RATING VOLTAGE	200V AC/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR CONTACT)	0.3A AC/DC (PER CONTACT PIN) IN CASE OF APPLYING 0.5A PER CONTACT PIN, THE TOTAL CURRENT OF THE WHOLE CONNECTOR SHALL BE 15.0A OR LOWER.
OPERATING TEMPERATURE	233~378K(-40°C~+105°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 60mohm MAX. / AFTER TEST : $\triangle$ 40mohm MAX.
INSULATION RESISTANCE	INITIAL : 100Mohm MIN. / AFTER TEST : 100Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	30 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	30P : 18.0N MAX. 40P : 24.0N MAX. 50P : 30.0N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	30P : 3.0N MIN. 40P : 4.0N MIN. 50P : 5.0N MIN.
COPLANARITY	0.10 MAX.
PRODUCT SPECIFICATION	PRS-2527
TEST REPORT	TR-18083
PACKING STANDARD	300-997
INSTRUCTION MANUAL	HIM-12003
APPEARANCE CRITERIA No.	QLS-A***

Rev.3




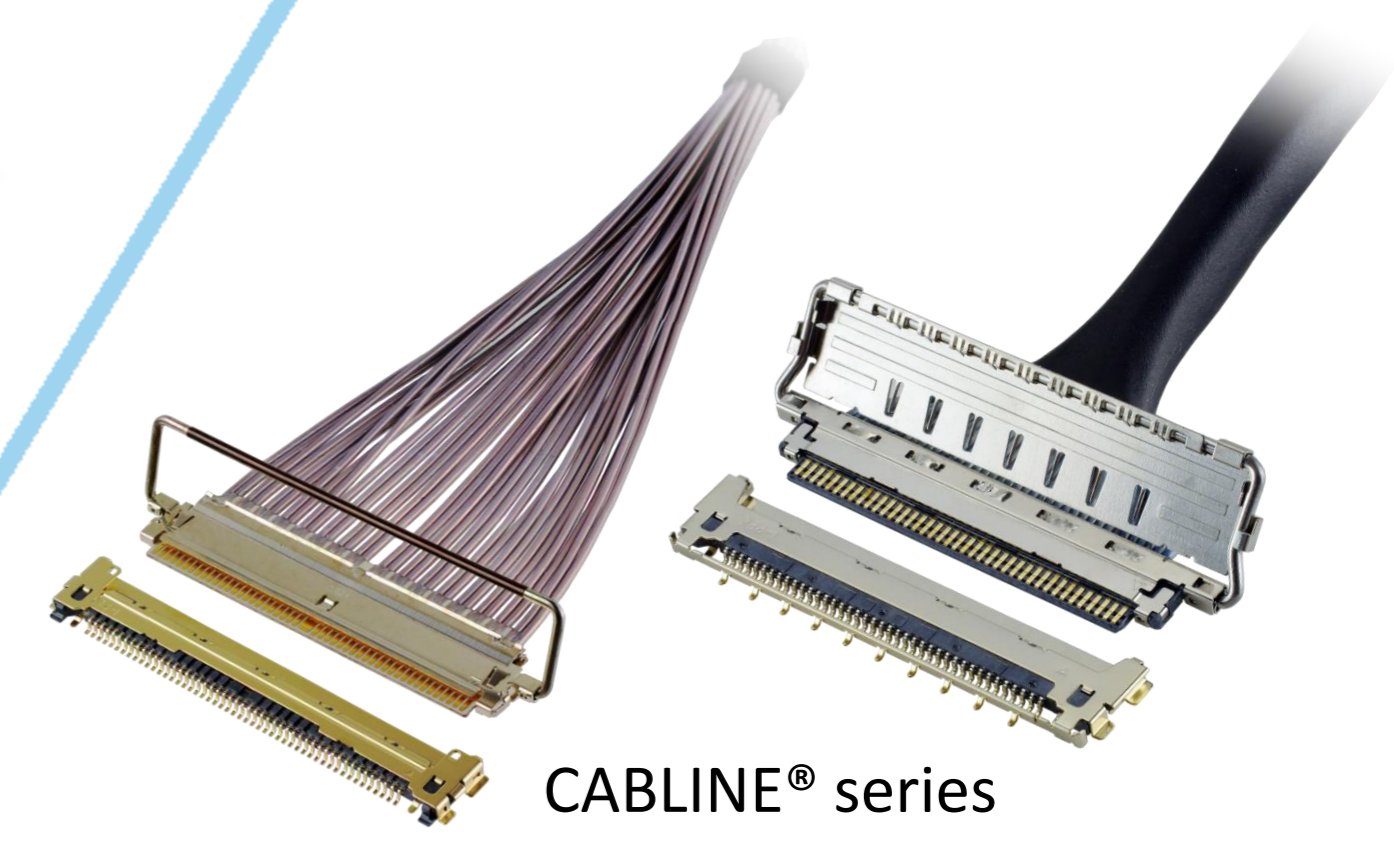
# Custom Connectors Available

 RF Connector

MHF® series



 CABLINE® series  
Micro-coaxial/Twinax/  
Discrete Wire Connector



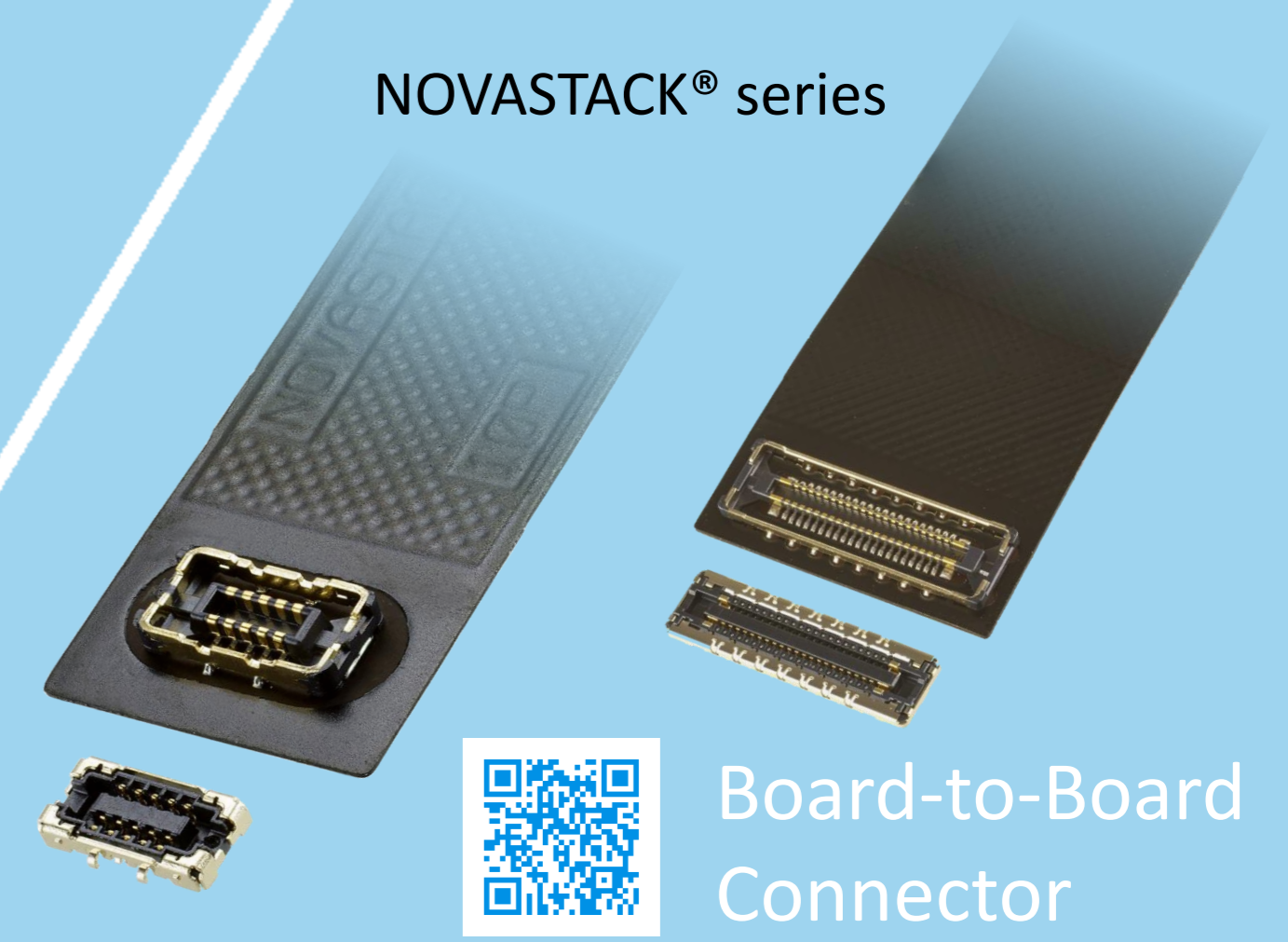
 Optical Module

LIGHTPASS® series



NOVASTACK® series

 Board-to-Board Connector



 Power Connector/  
Terminal

AP series

ISH® series



MINIFLEX® series

EVAFLEX® series

 FPC FFC Connector

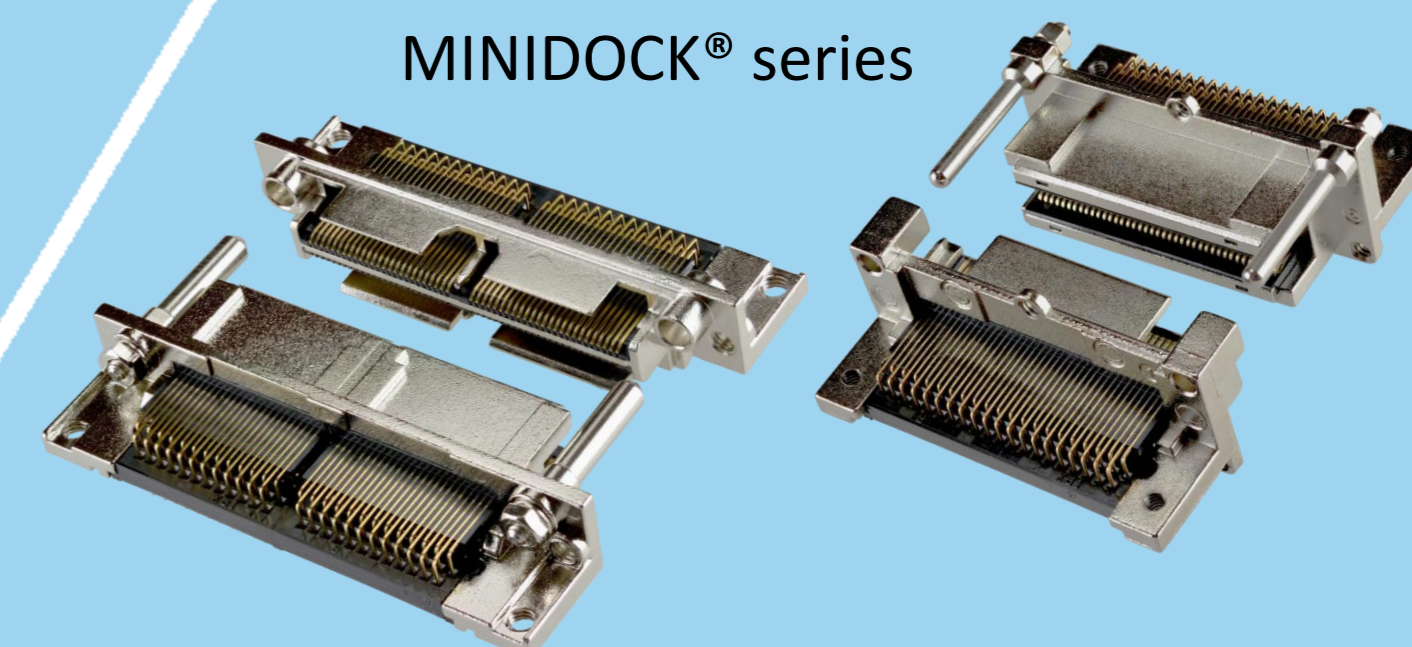


Inquiry



MINIDOCK® series

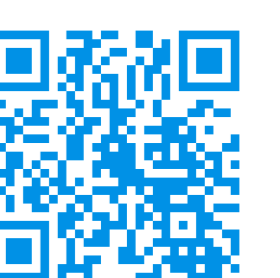
 I/O Connector



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